贸泽电子 MOUSER ELECTRONICS

samtec

Connector Solutions for Semiconductor Industry

FAE
Seven Qi & Marcus Hu
August 2022

INNOVATIVE TECHNOLOGIES. SUDDEN SERVICE . GLOBAL REACH

AGENDA

- **Company Overview**
- **Silicon to Silicon Solutions**
  - High Speed B-B
  - High Speed Cable
  - Optics
  - RF
  - Micro/Rugged
  - Flexible Stacking

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ABOUT US

Founded in 1976, Samtec is much more than just another connector company, we put people first
with a commitment to exceptional service and quality products. We believe that taking care of our customers and our employees is paramount in how we approach our business. This belief is deeply ingrained throughout Samtec and means that you can expect **exceptional service** coupled with **technologies** that take the industry further

GLOBAL REACH

HEADQUARTERS
NEW ALBANY, IN
USA

40 LOCATIONS

125+ COUNTRIES SERVED

8,000+ EMPLOYEES

PRIVATELY
OWNED COMPANY

SUDDEN SERVICE

1Reserve SHIPS TOMORROW — MORE THAN 200k PART NUMBERS SHIP IN 1 DAY

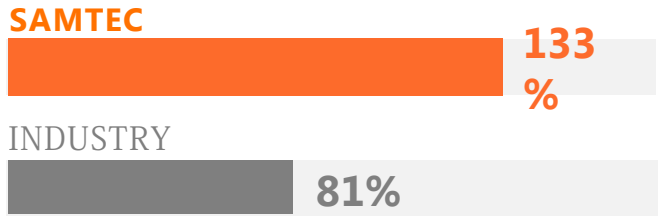
24HOUR SUDDEN SAMPLE — 24-HOUR FREE SAMPLES

2DAYS WORLD DIRECT — 2 DAYS TRANSIT TO ALL MAJOR MARKETS

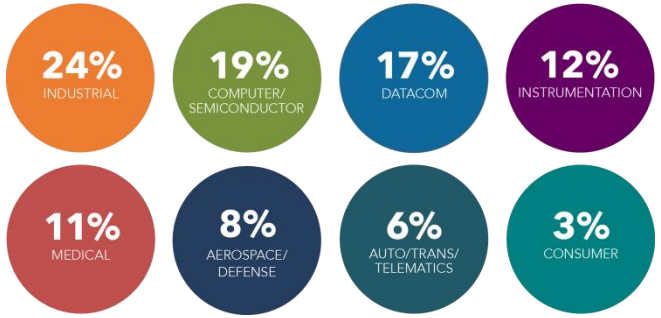
Bishop The Bishop Report — **#1** CONNECTOR MANUFACTURER

INDUSTRY UPDATE

SALES GROWTH (10-year span)



MARKETS SERVED



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BUSINESS MODEL

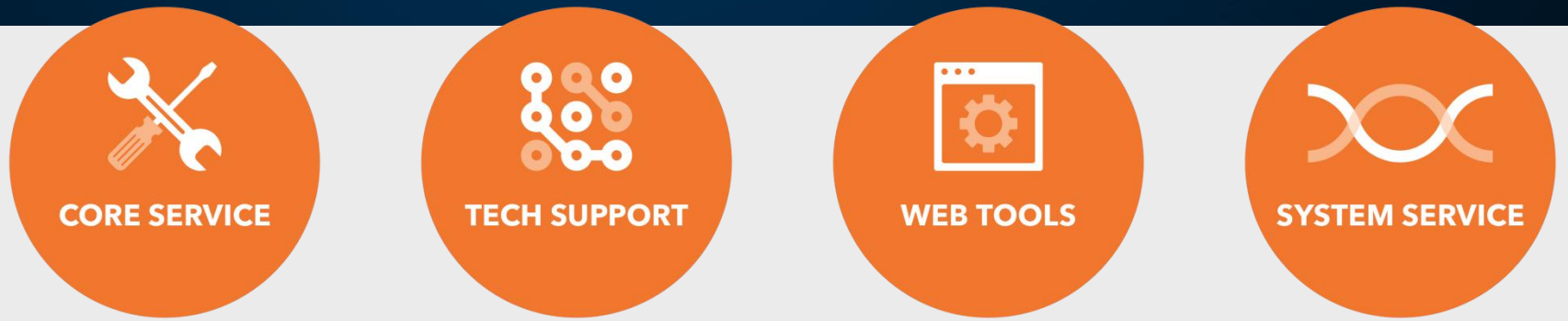
SILICON-TO-SILICON

- HIGH-SPEED BOARD-TO-BOARD
- OPTICS
- HIGH-SPEED CABLES
- RF

CORE BOARD-TO-BOARD

- MICRO/RUGGED
- FLEXIBLE STACKING

SUDDEN SERVICE



GLOBAL INFRASTRUCTURE

SALES | ENGINEERING | OPERATIONS | QUALITY | DIGITAL BIZ

GLOBAL SUPPORT NETWORK

1 DESIGN CENTERS

1 OPERATION FACILITIES

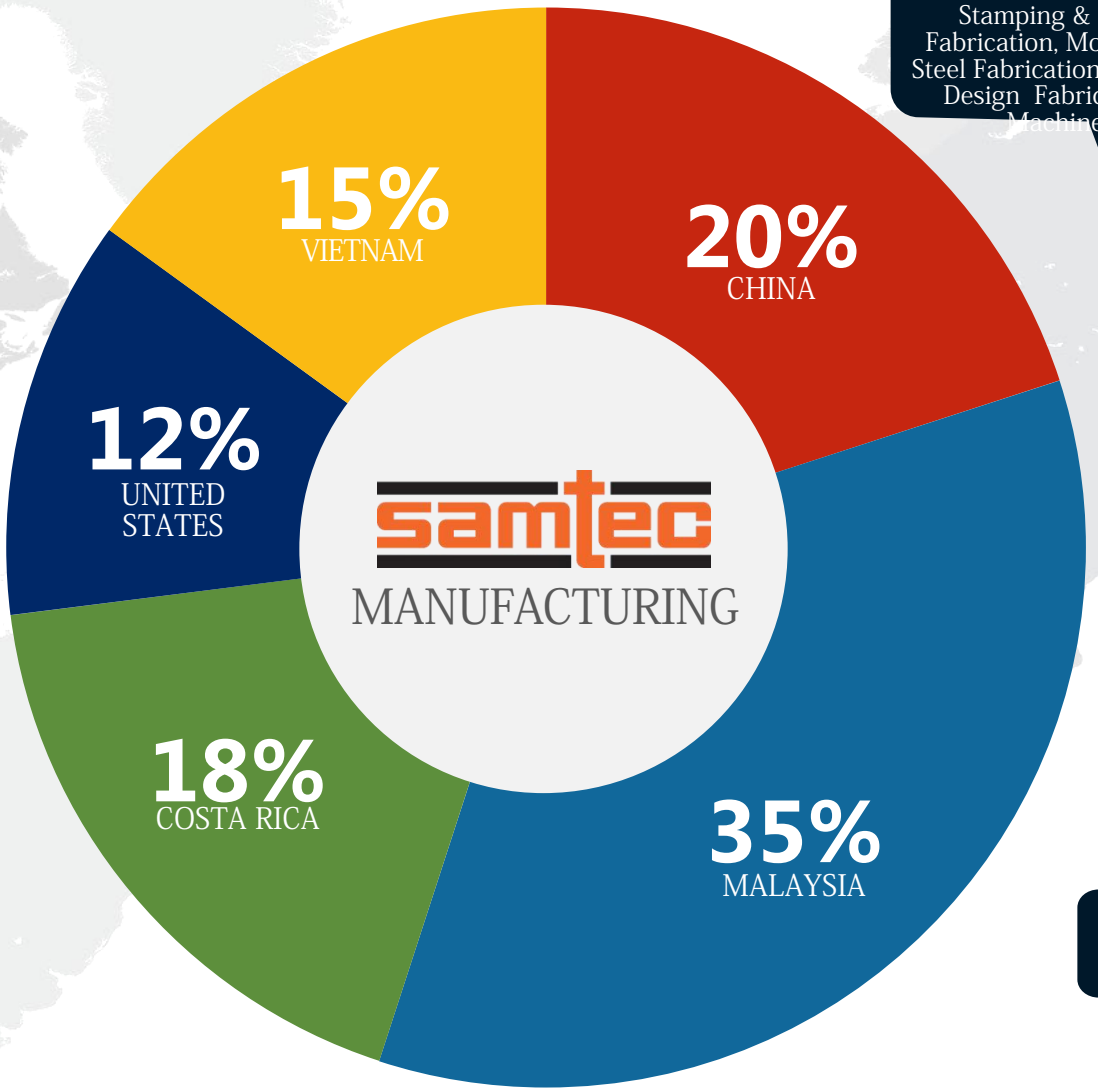
2 SALES OFFICES

125+ SALES SUPPORT

8K+ GLOBAL EMPLOYEES

MANUFACTURING MIX

GLOBAL BALANCE / DUAL OPERATIONS



SAMTEC USA
Board-to-Board, High-Speed Cable, Active Optical Cable, GCT, Machine, Tooling Design & Fabrication, Outside Sourcing/Vendor Base, Stamping & Steel Fabrication, Molding & Steel Fabrication, RF Production, Electroplating

SAMTEC CABLE
High-Speed Cable, Design & Development, R&D & Manufacturing of Precision Extruded Cable

SAMTEC MICROELECTRONICS
Active Optical Engines,

SAMTEC COSTA RICA
Board-to-Board, High-Speed Cable, Electroplating

SAMTEC DG
Stamping & Steel Fabrication, Molding & Steel Fabrication, Tooling Design Fabrication, Machine

SAMTEC HUIZHOU
Board-to-Board, High-Speed Cable, Machine, Tooling Design & Fabrication, Outside Sourcing/Vendor Base Electroplating

SAMTEC TAIWAN
High-Speed Cable, RF Design & Development, RF Production

SAMTEC VIETNAM

SAMTEC PENANG
Board-to-Board,

SAMTEC JOHOR BAHRU
Board-to-Board

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MARKETS SERVED I PERCENT OF SALES

Based on 2021 Sales

INDUSTRIAL

24%

COMPUTER/ SEMICONDUCTOR

19%

DATACOM

17%

INSTRUMENTATION

12%

MEDICAL

11%

AERO/ DEFENSE

8%

AUTO/TRANS/ TELEMATICS

6%

CONSUMER

3%

Customer Base of 50,000

25,000 (Direct) + 25,000 (Digital)

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SUDDEN SERVICE®

www.SAMTEC.com

Samtec has developed innovative search, design, and validation tools to help customers quickly and easily find the right solution. Search by product name, characteristics, pictures, or build an assembly by entering physical specifications.

Online Tools

FIND, DESIGN & VALIDATE YOUR SOLUTION

Solutionator®

DESIGN IN A MINUTE

Quickly build mated connector sets and cable assemblies using a wide variety of user-defined search parameters and filters.

Picture Search

VISUALLY FIND YOUR SELECTION

Browse through Samtec's most popular products to find the ideal solution for your application.

Downloads

3D MODELS, SPECS, PRINTS & MORE

3D Models

QUICK DOWNLOADS

Quickly configure, preview and download models in more than 150 different formats, including AutoCad, Solid Edge, Inventor and many more.

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Samtec's user-friendly eCommerce platform allows you to quickly and easily check product availability and pricing, as well as place and manage your orders online.

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SILICON-TO-SILICON™ CONNECTIVITY SOLUTIONS

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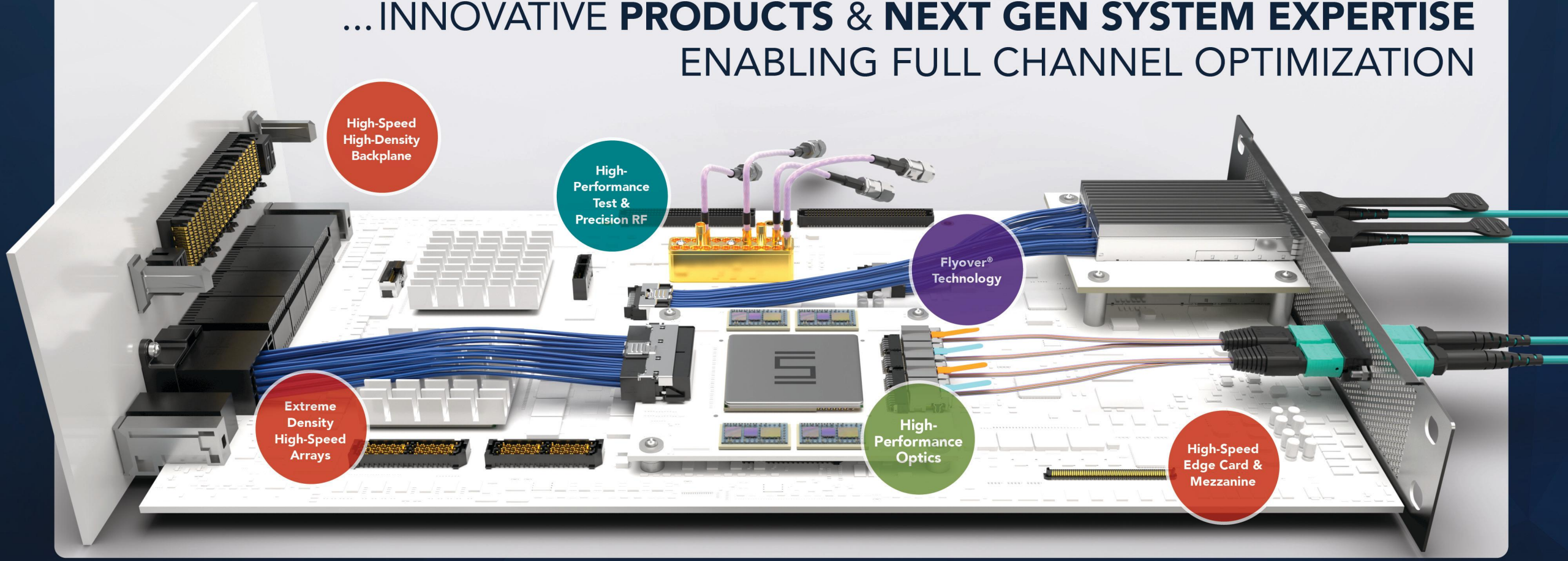
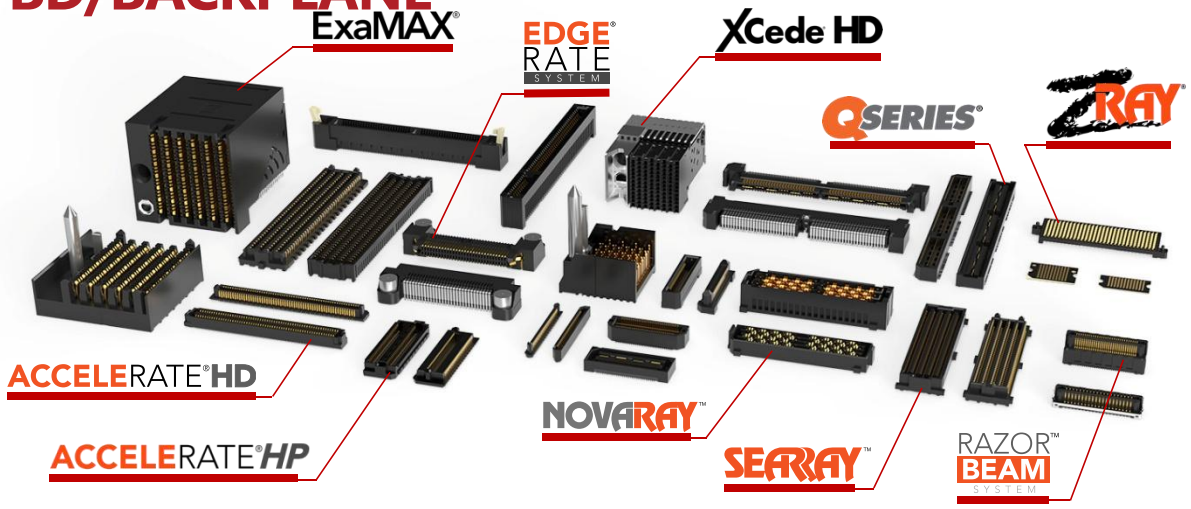
...INNOVATIVE **PRODUCTS** & **NEXT GEN SYSTEM EXPERTISE** ENABLING FULL CHANNEL OPTIMIZATION



HIGH-SPEED BD-TO-BD/BACKPLANE

OPEN-PIN-FIELD ARRAYS GROUND PLANE STRIPS EDGE CARDS
ULTRA-MICRO BACKPLANE

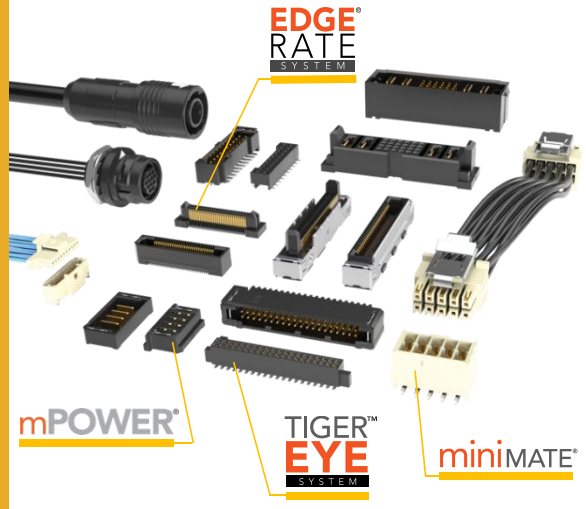


HIGH-SPEED CABLE

SAMTEC FLYOVER™ MID-BOARD & PANEL
BACKPLANE MICRO COAX & TWINAX

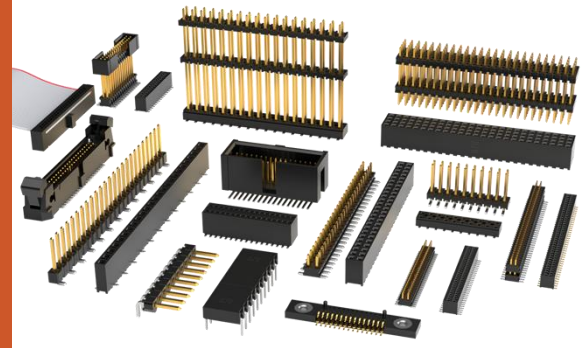
MICRO/RUGGED

RUGGED CONTACT SYSTEM FLEX POWER
RUGGED SI MICRO SEALED I/O



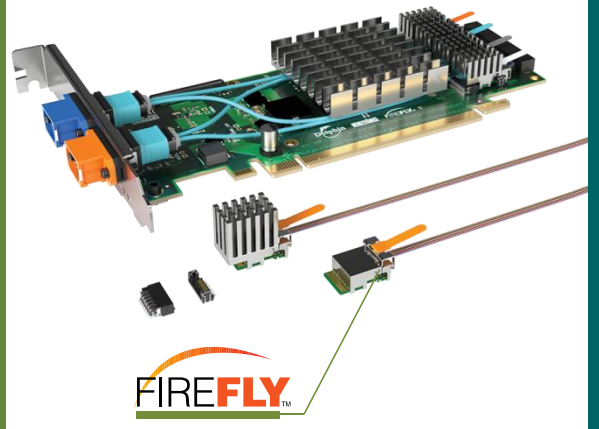
FLEXIBLE STACKING

LOW PROFILE PASS-THROUGH ONE-PIECE
SKYSCRAPERS SHROUDED HEADERS IDC
SYSTEMS



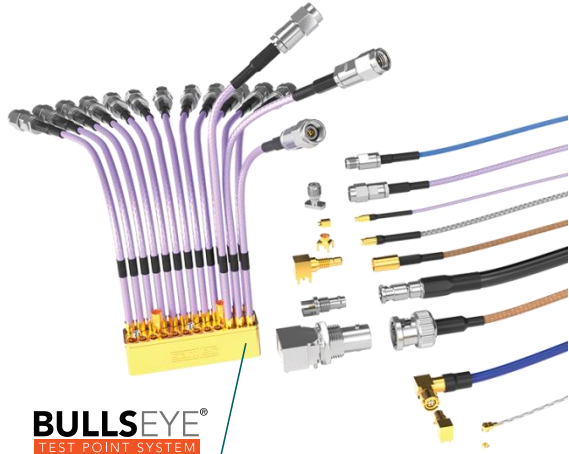
OPTICS

MICRO FLYOVER SYSTEMS EXTENDED TEMP
PCIe®-OVER-FIBER I/O INTERFACES



RF

PRECISION RF 50 Ω SOLUTIONS 75 Ω
SOLUTIONS ORIGINAL SOLUTIONS



LOW PROFILE GROUND PLANE CONNECTORS

- 0.50 mm, 0.635 mm and 0.80 mm pitch
- 5 mm to 25 mm stack heights
- Integral ground/power plane
- Compatible with mPOWER® (UMPT/UMPS) for power/signal flexibility
- Differential pairs and edge mount options available

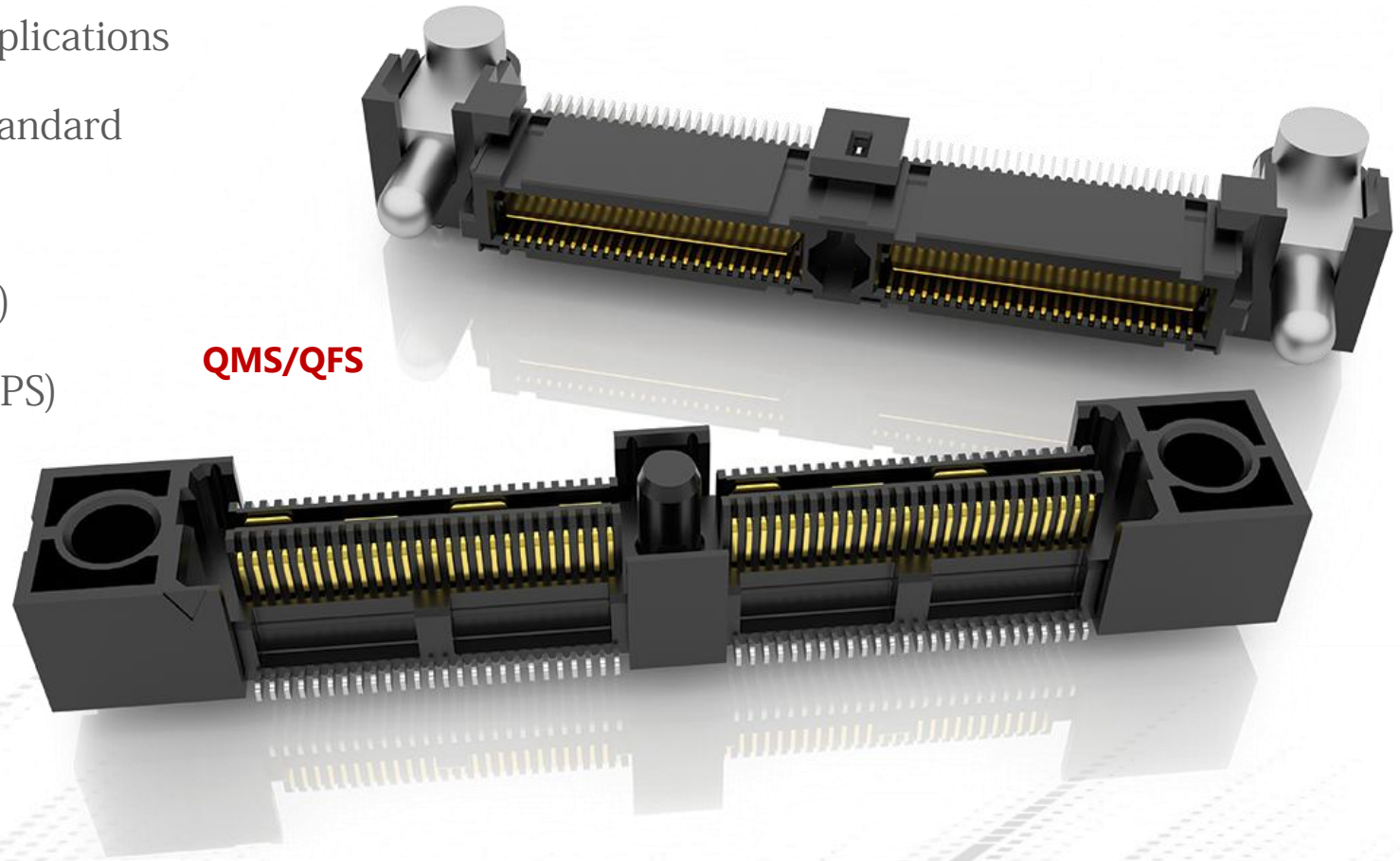
QSTRIP®

28 Gbps

MAX 25 Amps

RUGGED GROUND PLANE CONNECTORS

- 0.635 mm pitch
- Increased insertion depth for rugged applications
- Up to 156 signal pins/48 signal pairs standard
- Vertical, right-angle and edge mount
- Shielded systems available (QMSS/QFSS)
- Compatible with mPOWER® (UMPT/UMPS) for power/signal flexibility



Q2™ 25 Gbps MAX 15.7 Amps

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EDGE RATE®CONNECTOR STRIPS

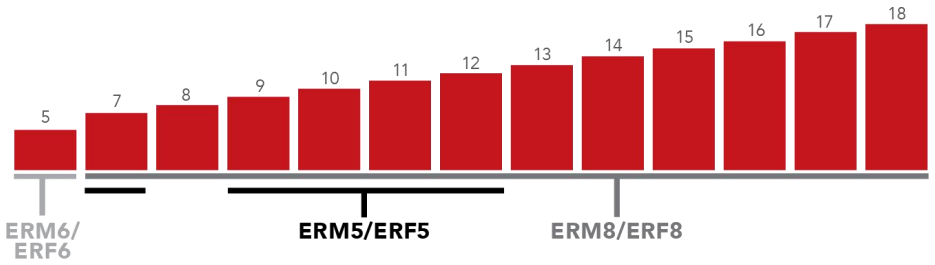
OPTIMIZED FOR SPEED • HIGH CYCLES • INCREASED CONTACT WIPE

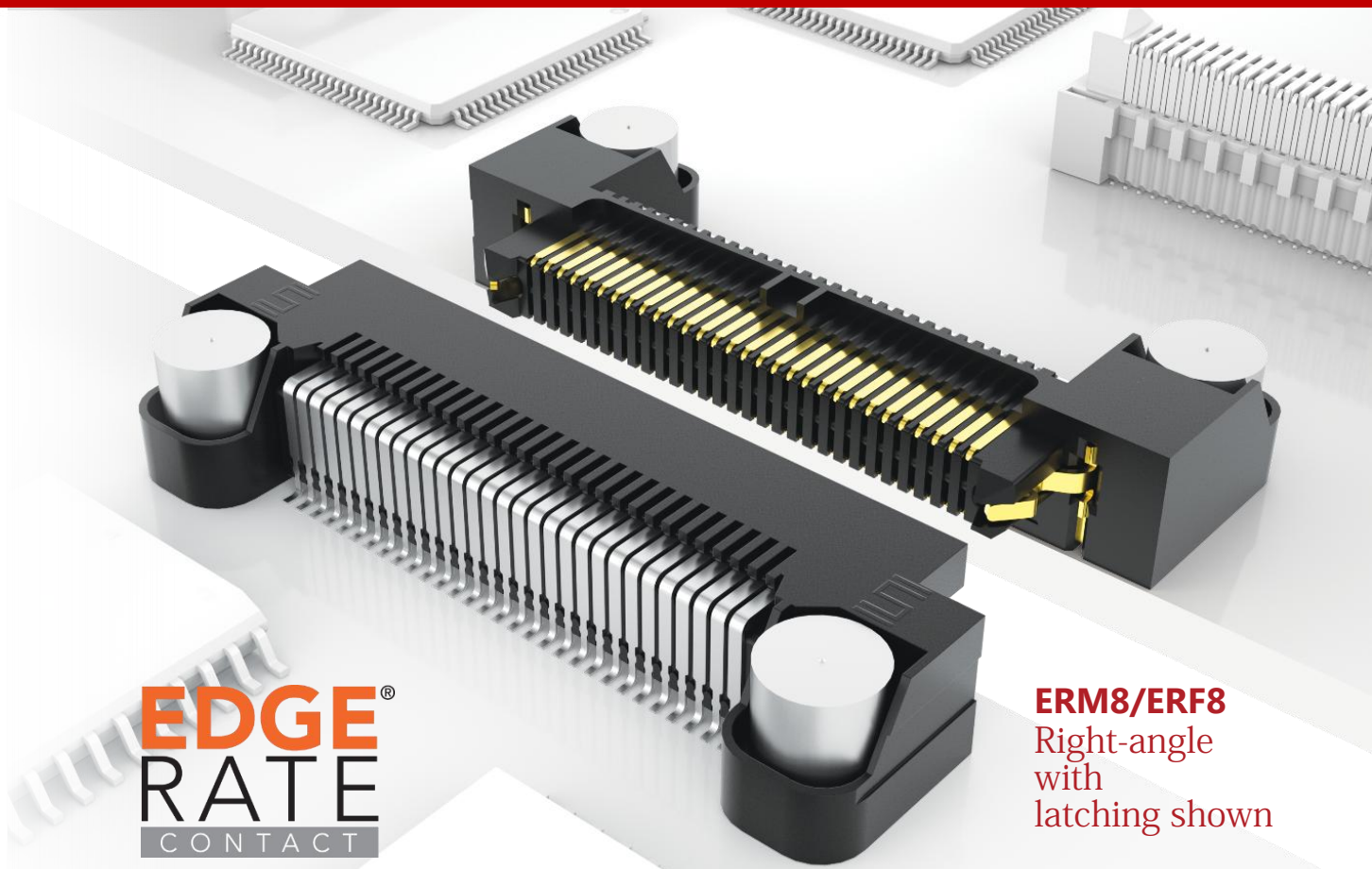
EDGE RATE® CONTACT SYSTEM:

- Smooth milled mating surface reduces wear and increases durability
- Lower insertion and withdrawal forces
- Robust when “zippered” during unmating
- Minimized parallel surface area reduces broadside coupling and crosstalk
- Designed, simulated and optimized for 50 Ω and 100 Ω systems

STACK HEIGHT FLEXIBILITY

(Size in mm)





ERM8/ERF8
Right-angle
with
latching shown

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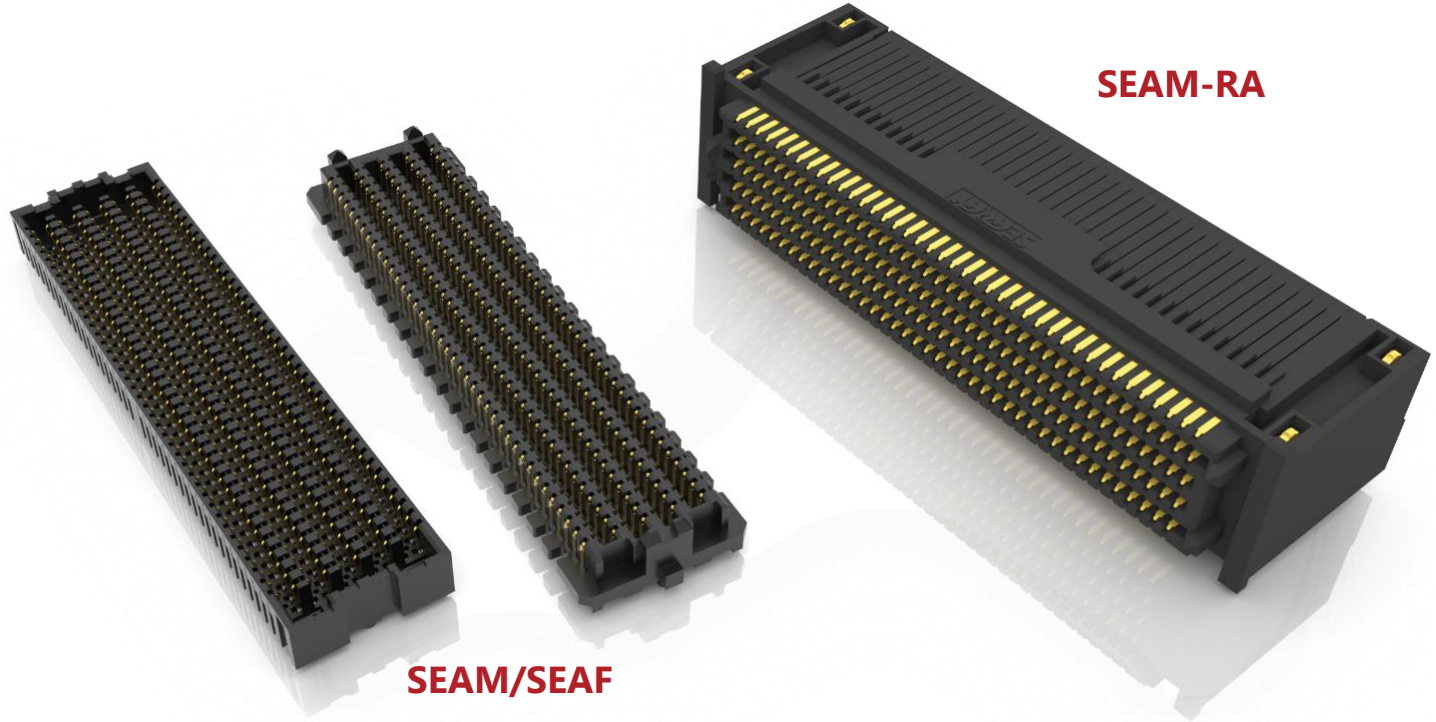
1.27mm / 0.8 mm PITCH ARRAYS

- Maximum grounding and routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance
- 7 mm to 40 mm stack heights; right-angle available
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel and InfiniBand™

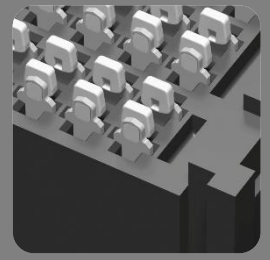
SEARAY™

NRZ 28 Gbps

PAM4 56 Gbps

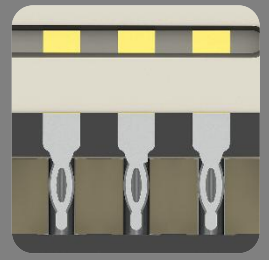


1.12 mm (.044") contact wipe



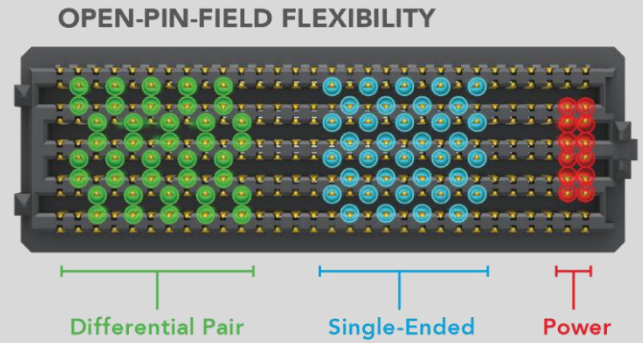
Solder charge terminations (IPC-A-610F & IPC J-STD-

Elevated stack heights available (SEAR)



Press-fit tails available (SEAMP/SEAFP)

Jack screw standoffs (JSO)



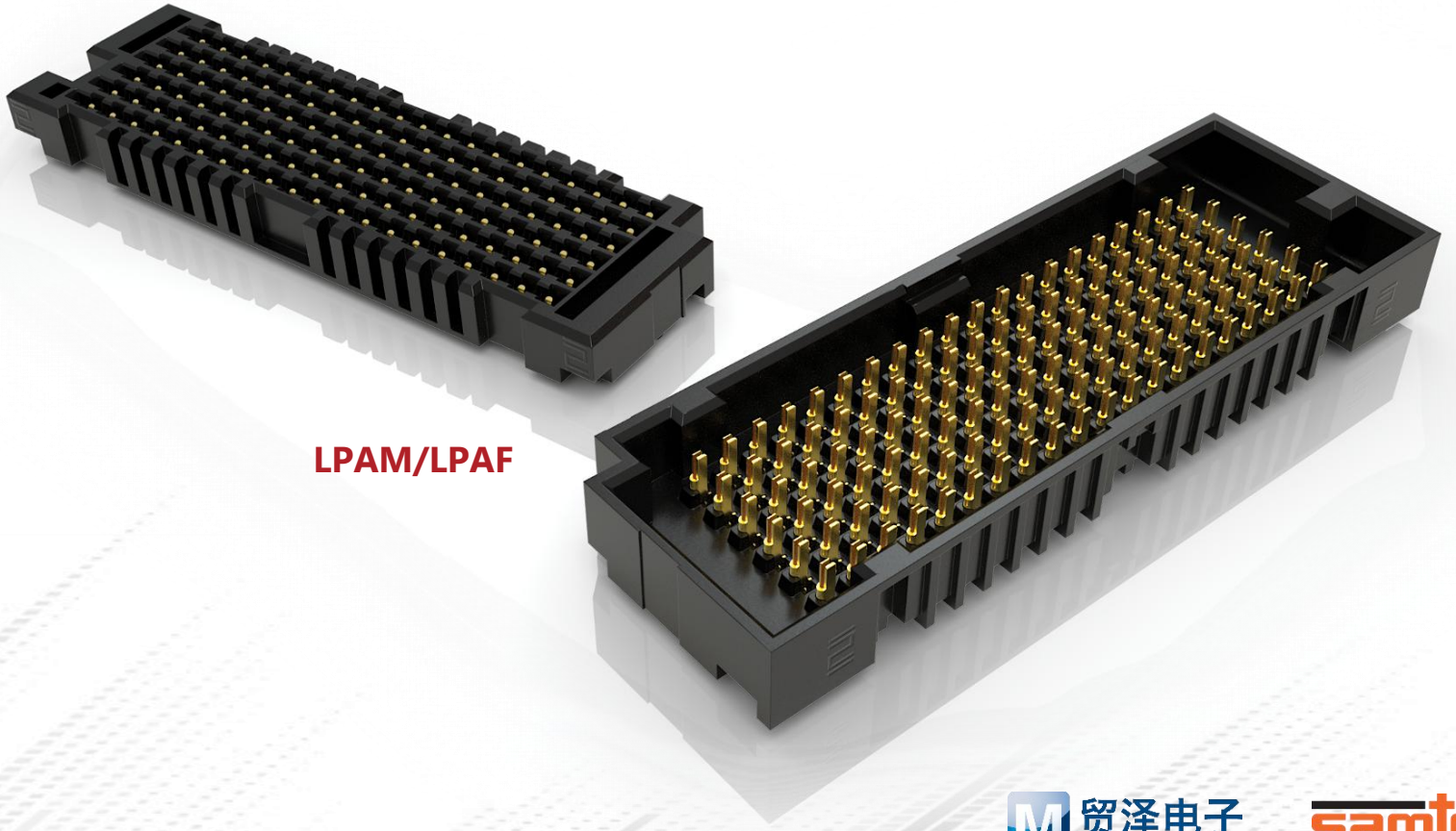
LOW PROFILE ARRAYS

- Up to 400 total pins in 4, 6 or 8 rows
- 4 mm, 4.5 mm and 5 mm stack heights
- 1.27 mm pitch
- Solder crimped termination for ease of processing
- Press-in or threaded standoffs available to assist with unmating (JSO)
- Compatible with mPOWER® for power/signal flexibility

LP ARRAY™

NRZ 28 Gbps

PAM4 56 Gbps



LPAM/LPAF

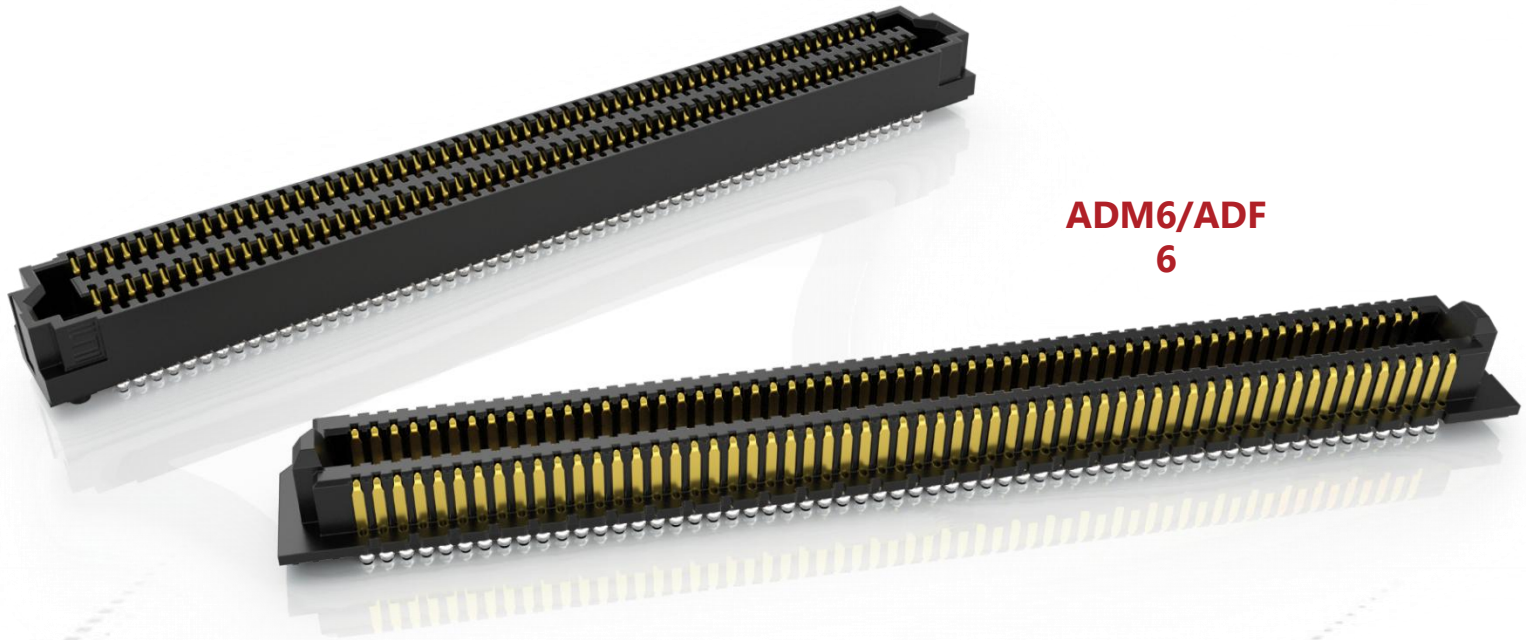
Dual blade contact
with solder crimp tail

HIGH-DENSITY ARRAYS

- Up to 400 I/Os in a 4-row design
- Open-pin-field design for grounding and routing flexibility
- 0.635 mm pitch Edge Rate® contacts
- Low profile 5 mm stack height and slim 5 mm width
- Other stack heights in development
- PCIe® 5.0 capable
- Compatible with mPOWER® for power/signal flexibility

ACCELERATE® HD

PAM4 56 Gbps



ADM6/ADF6

Right-angle in development (ADF6-RA)

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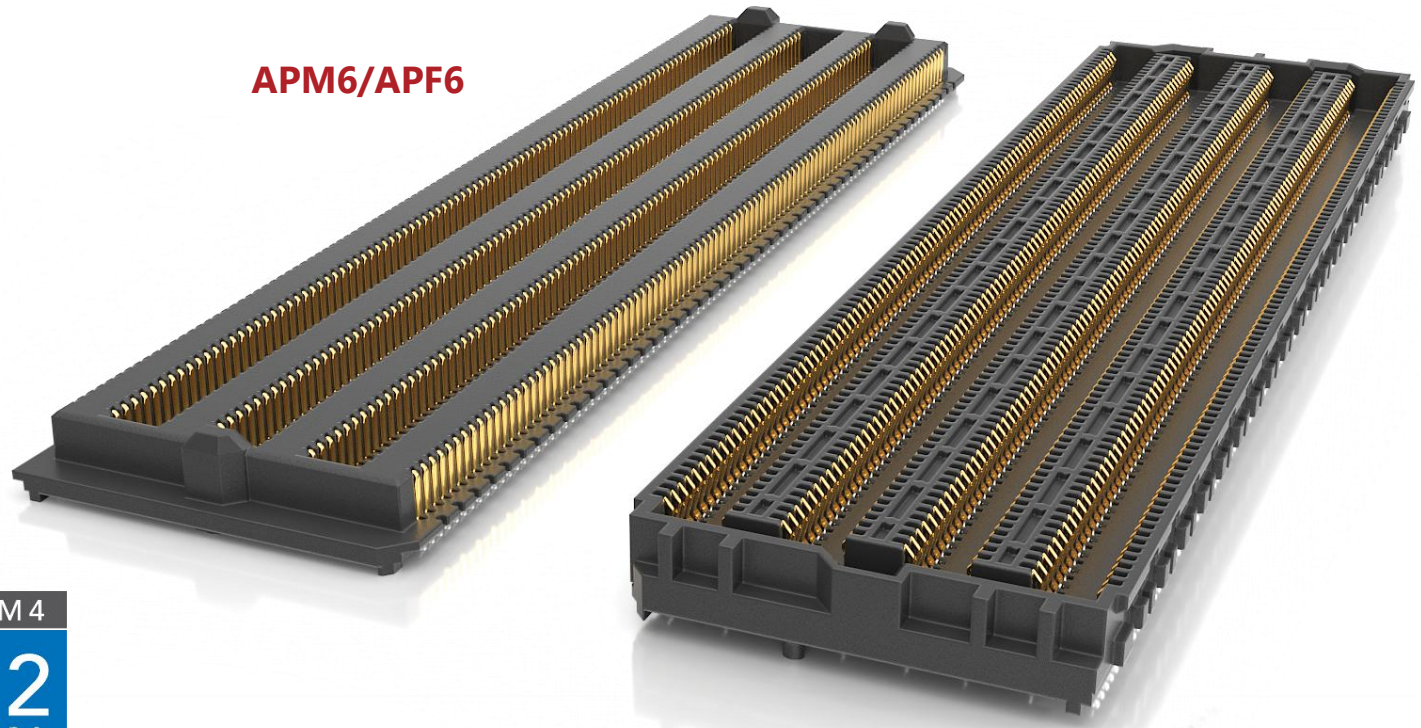
HIGH-PERFORMANCE ARRAYS

- Flexible open-pin-field and cost optimized, extreme performance solution
- Low-profile 5 mm stack height and up to 10 mm
- 0.635 mm pitch
- Four row design with up to 400 total pins; roadmap to 1,000+ pins
- Data rate compatible with PCIe® 5.0 and 100 GbE
- Cable assembly with up to 96 pairs in development

ACCELERATE®HP

NRZ 56 Gbps

PAM4 112 Gbps

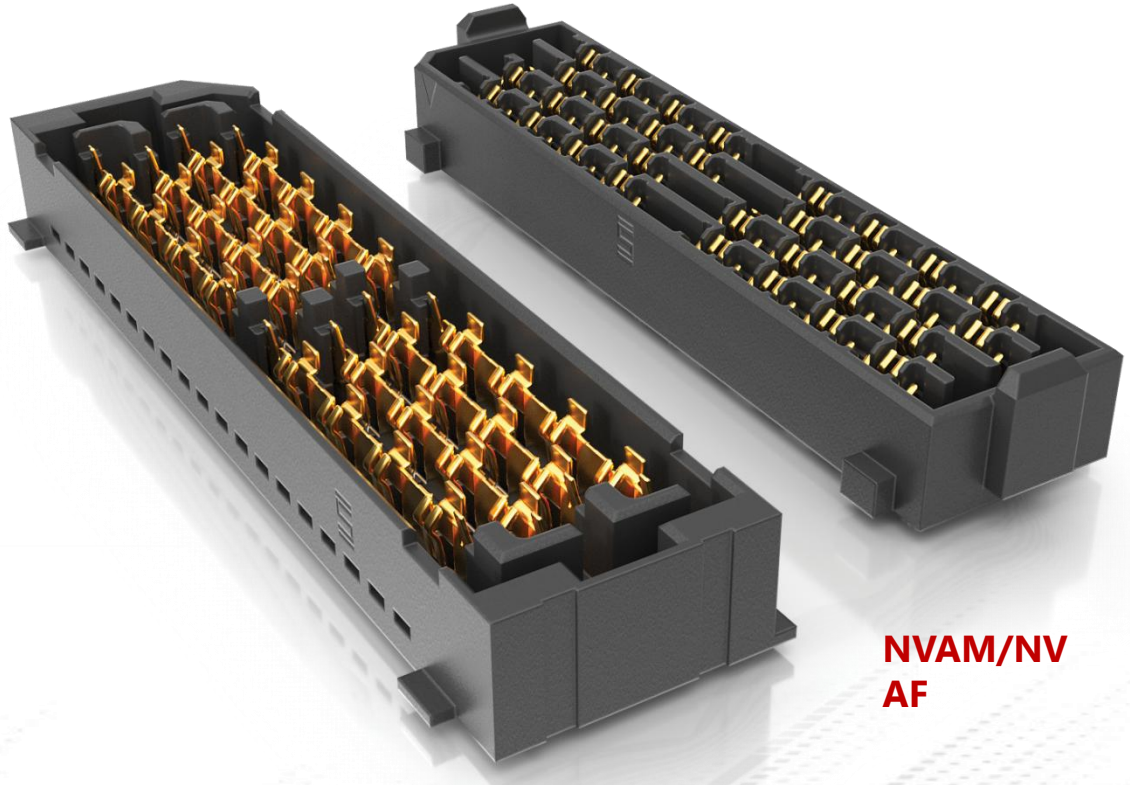


EXTREME PERFORMANCE ARRAYS

- 4.0 Tbps aggregate data rate - 9 IEEE 400G channels
- Two points of contact ensure a more reliable connection
- Fully shielded differential pair design
- Extremely low crosstalk (to 40 GHz) and incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- Utilizes 40% less space with the same data throughput as compared to traditional arrays
- Terminal with latching available to mate with NovaRay® cable (NVAM-C)

NOVARAY®

NRZ 56 Gbps | PAM4 112 Gbps



NVAM/NV AF

Mating assembly with 34 AWG Eye Speed® ultra low skew twinax cable

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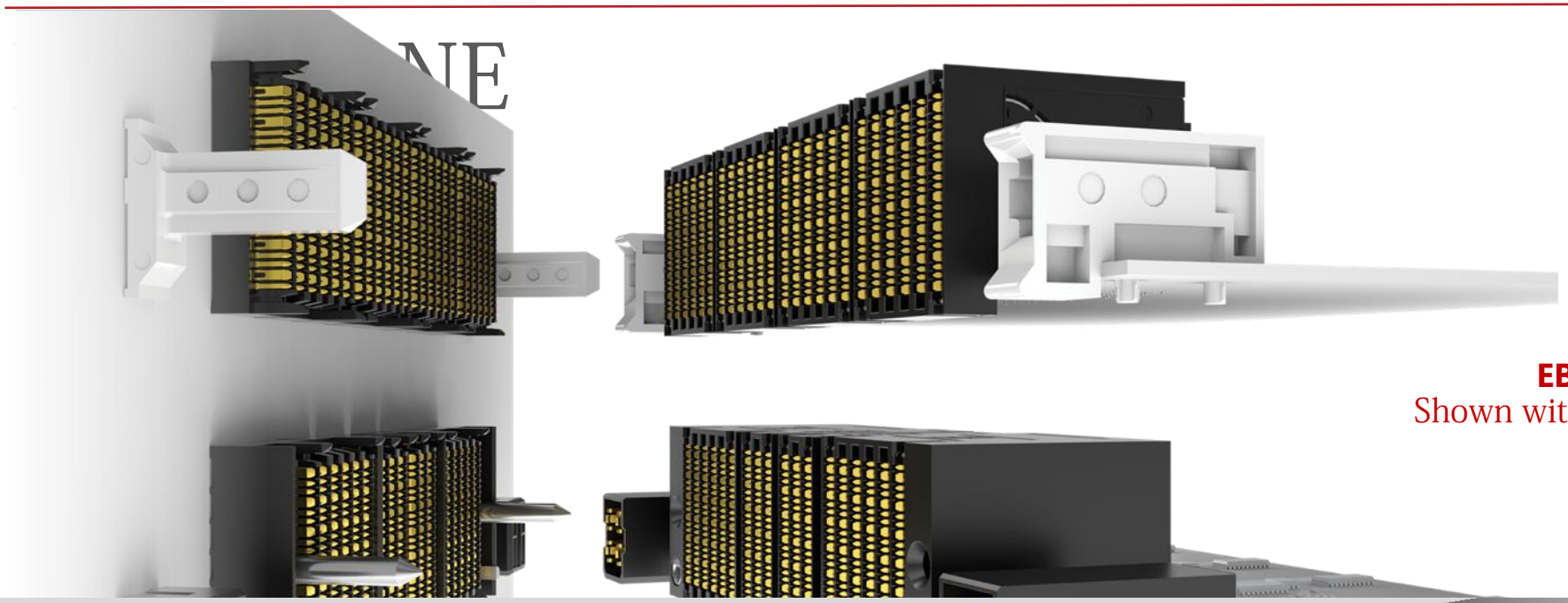
HIGH-SPEED AND HIGH-DENSITY

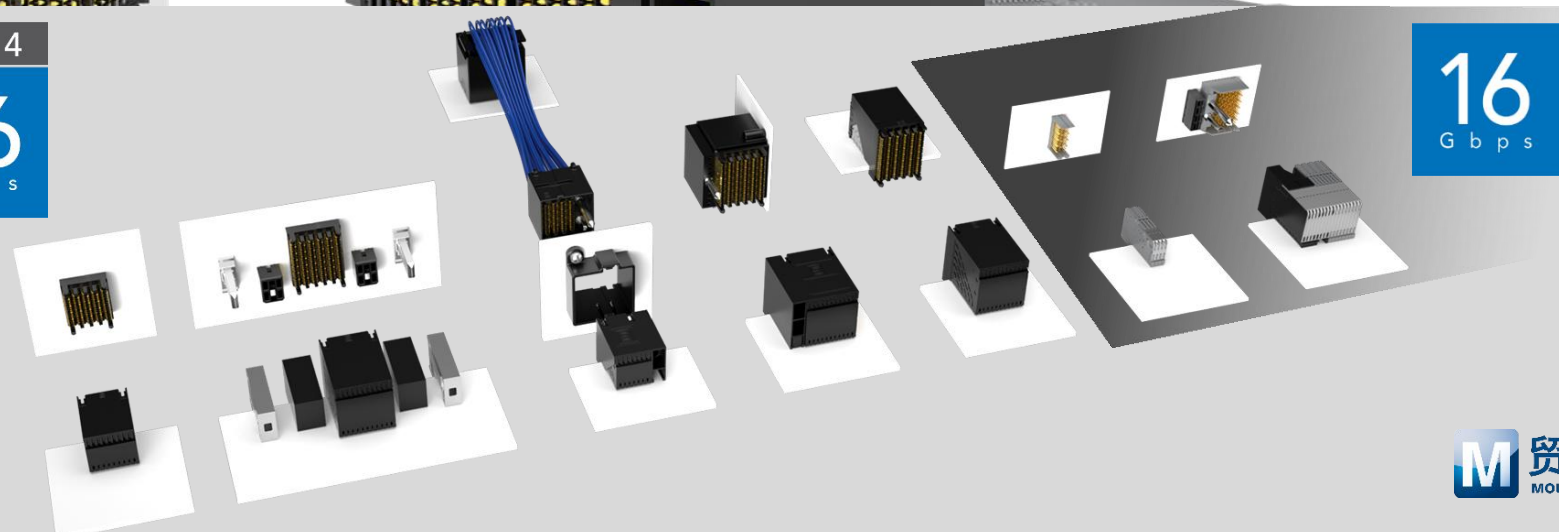


EBTM/EBTF-RA
Shown with power and guidance modules

ExaMAX® HIGH-SPEED

PAM4 56 Gbps

- Traditional Backplane
- Add-on Power & Discrete Guidance Modules
- Cable Systems
- Direct-Mate Orthogonal
- Coplanar



XCede® HD HIGH-DENSITY

16 Gbps

- Traditional Backplane
- Modular Design with Guidance, Keying & Power Modules

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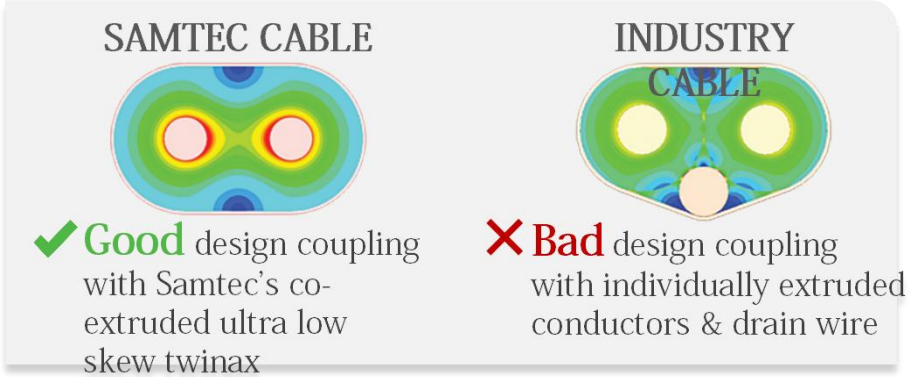
ULTRA LOW SKEW **TWINAX**

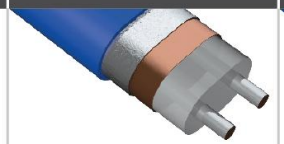
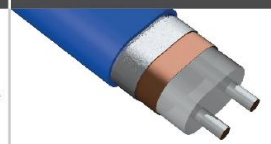
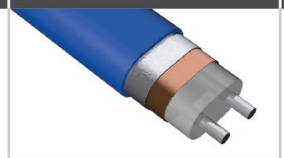
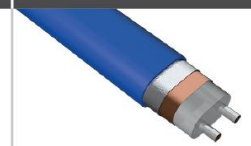
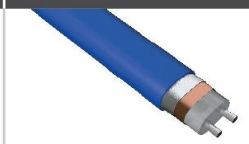
MICRO CELLULAR DIELECTRIC EXTRUSION

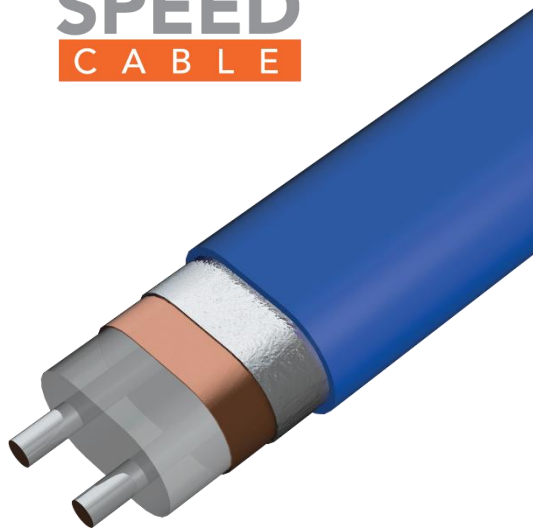
- Critical dimensions measured at every dielectric spool
- Inline laser and CAPAC devices for capacitance monitoring and diameter control
- In-process stats summary sheet for Cpk acceptance



EYE® SPEED CABLE

NOMINAL PERFORMANCE SPECIFICATIONS

			28 AWG	30 AWG	32 AWG	34 AWG	36 AWG
Eye Speed® Ultra Low Skew Twinax Cable							
14 GHz (28G NRZ/ 56G PAM4)	0.25 m	IL (dB)	-1.0	-1.2	-1.5	-1.8	-2.2
	1.00 m		-4.1	-4.7	-5.9	-7.5	-8.9
28 GHz (56G NRZ/ 112G PAM4)	0.25 m		-1.5	-1.8	-2.2	-2.7	-3.2
	1.00 m		-6.1	-7.1	-8.7	-10.9	-12.7
Density/Flexibility			Good	Good	Better	Best	Best



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SAMTEC FLYOVER® TECHNOLOGY

THE PROBLEM

PCB REACH AT NEXT GEN SPEEDS

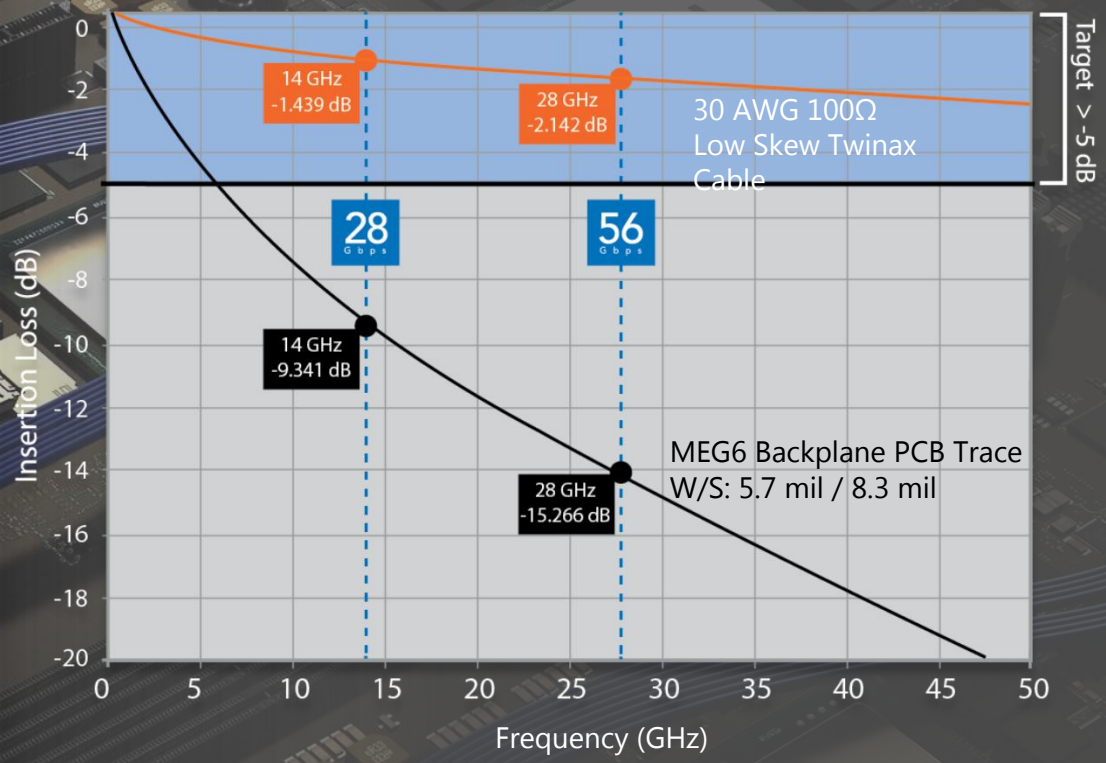
BANDWIDTH VS. TRADITIONAL & HIGH-SPEED MATERIALS

	FR408	MEGTRON 6	MICRO TWINAX	OPTICS
10 Gbps	up to 10"	10"+	up to 39"	100 m+
14 Gbps	up to 5"	up to 10"	up to 33"	100 m+
28 Gbps	up to 2"	up to 5"	up to 23"	up to 100 m
56 Gbps	0.0"	up to 2"	up to 12"	TBD
112 Gbps	0.0"	0.0"	up to 6"	TBD

(–5 dB Loss Target. Reach Estimate. For OIF VSR applications.)

THE SOLUTION

SAMTEC FLYOVER® SYSTEMS



FLYOVER® MID-BOARD ASSEMBLIES

ACCELERATE®

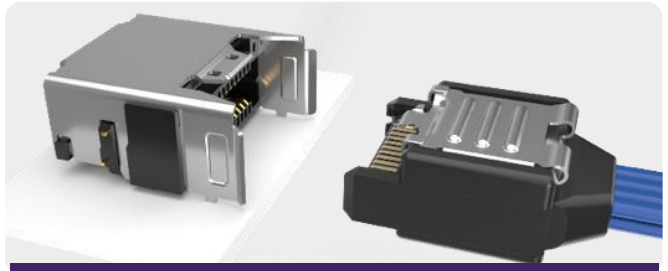
SLIM CABLE ASSEMBLY

Slimmest cable assembly in the industry - 7.6 mm body width

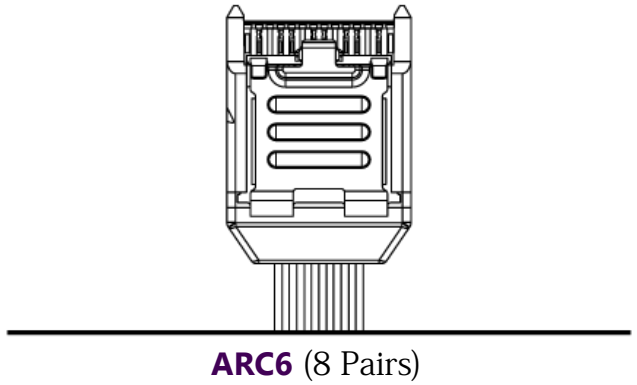
High-density 2-row design

8, 16 and 24 differential pair configurations

Eye Speed® 34 AWG ultra low skew twinax



Right-angle available



ARC6 (8 Pairs)

NRZ 28 Gbps

PAM4 56 Gbps

FLYOVER® MID-BOARD ASSEMBLIES

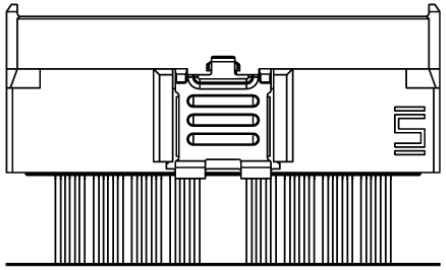
NOVARAY®

EXTREME HIGH-SPEED, HIGH-DENSITY CABLE

Industry leading aggregate data rate density - 2x the
data rate in 60% of the space

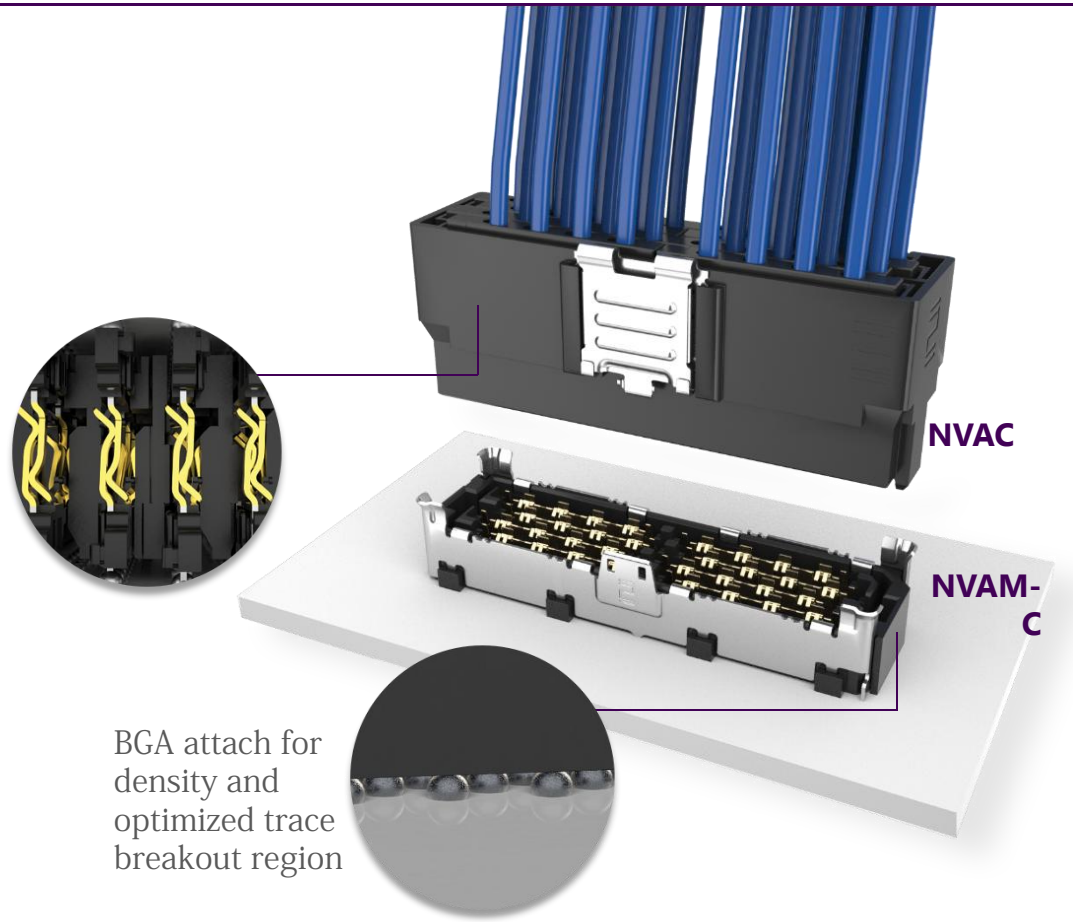
Proprietary pin to ground configuration enables very
low crosstalk (to 40 GHz) and very tight impedance control

NVAC
(2 Bank, 4 Row, 32 Pairs)



NRZ	PAM4
56 Gbps	112 Gbps

8 to 32 signal pairs with two reliable points of contact guaranteed;
72 pairs in development



BGA attach for density and optimized trace breakout region

贸泽电子 MOUSER ELECTRONICS

samtec

FLYOVER® MID-BOARD ASSEMBLIES

NOVARAY® I/O

NOVARAY® I/O ASSEMBLIES

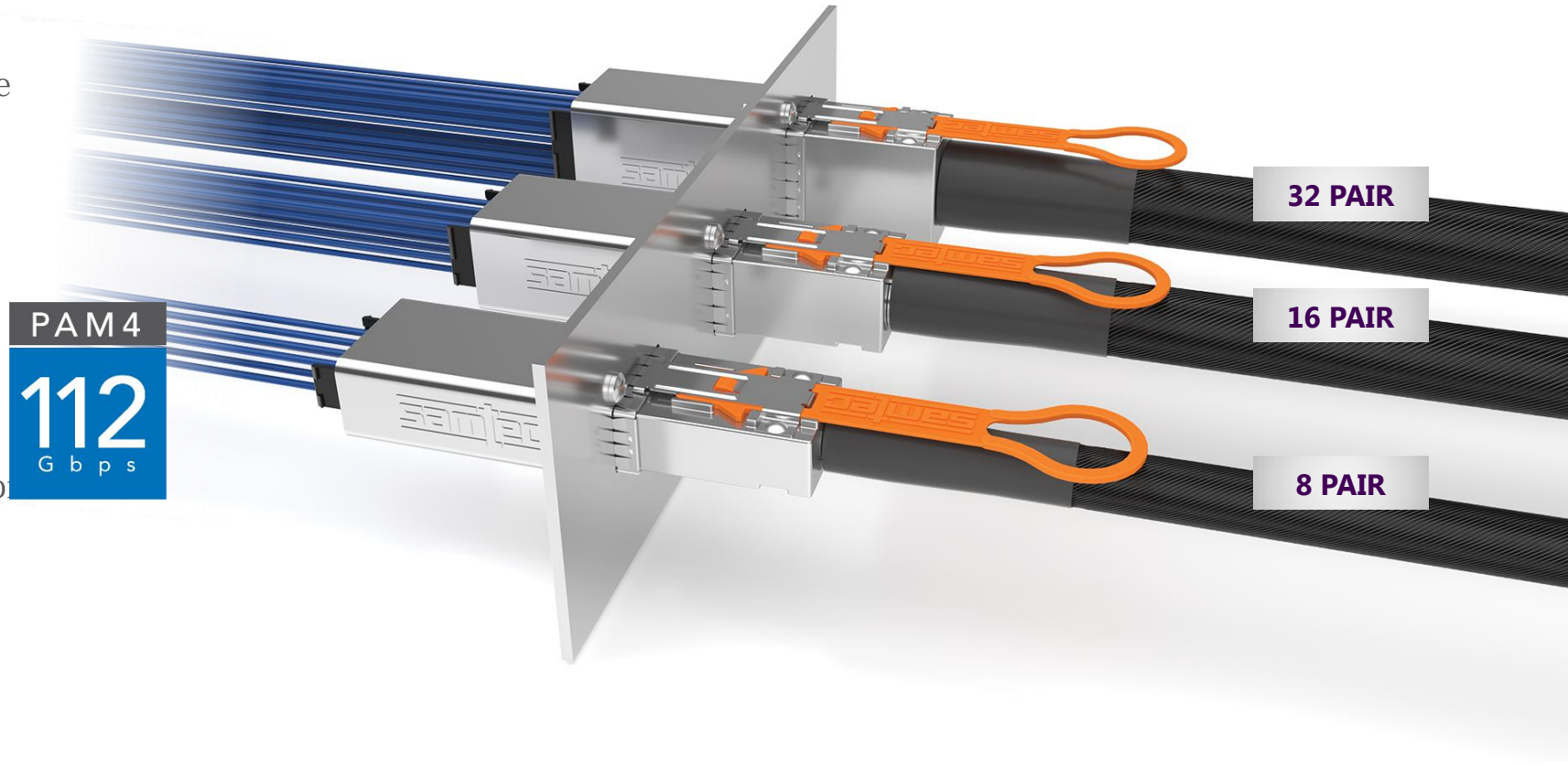
Up to 1024 Gbps PAM4 aggregate data rate

Cable-to-cable bulkhead panel connection

112 Gbps PAM4 solutions in 16 and 32 pair configurations

PCI Express® 6.0 solutions in x4 and x8 pair configurations

Rugged external shielding for EMI protectio



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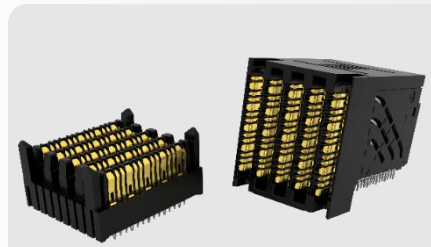
BACKPLANE CABLE ASSEMBLIES

HIGH-SPEED BACKPLANE CABLE

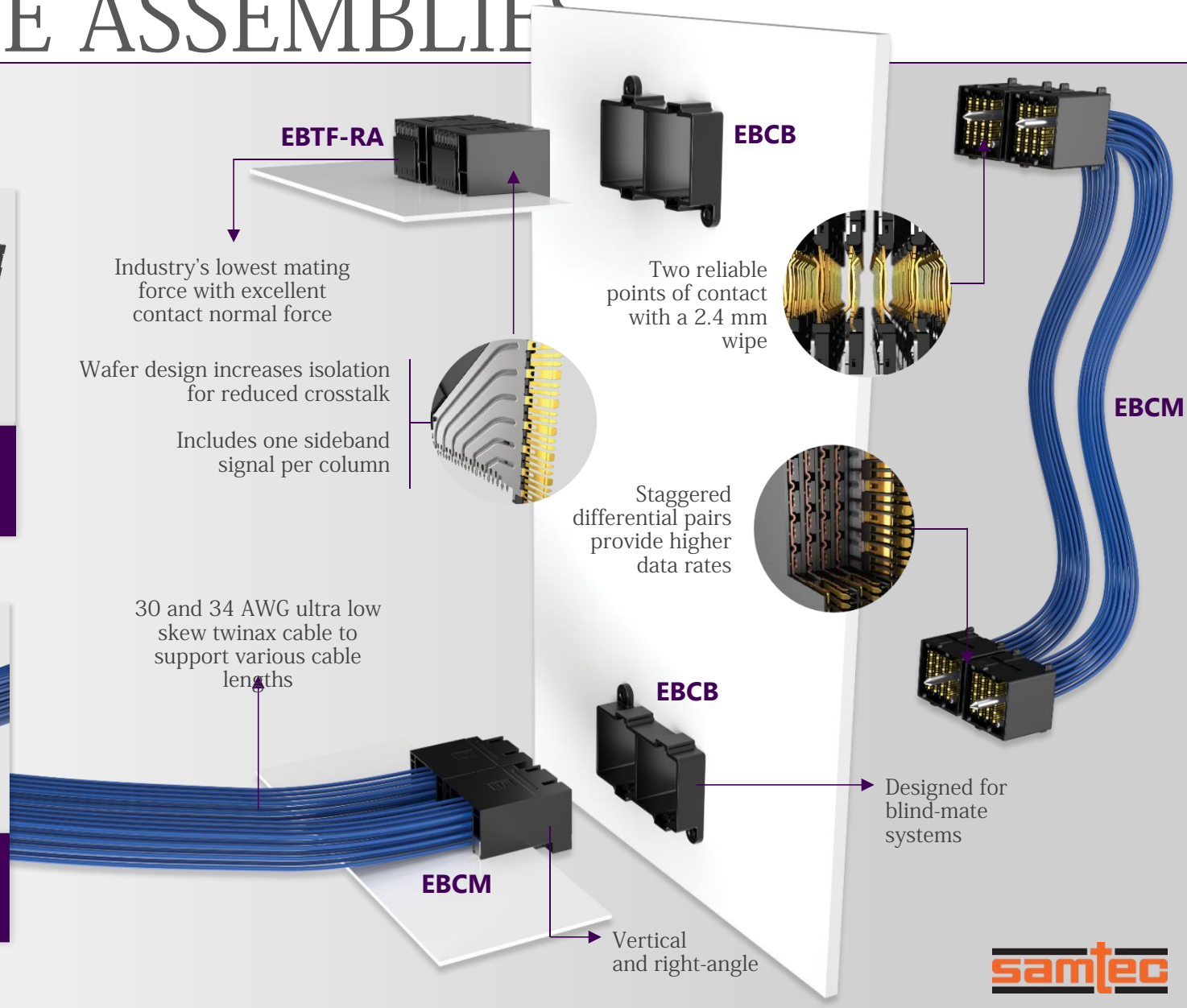
4 and 6 pairs;
4-16 columns



Intermateable with all ExaMAX® connectors (EBTM/EBTF–RA)

Integrated guidance and keying option

Cable-to-DMO (Direct Mate Orthogonal)



LOW PROFILE CO-PACKAGED CABLE SYSTEM

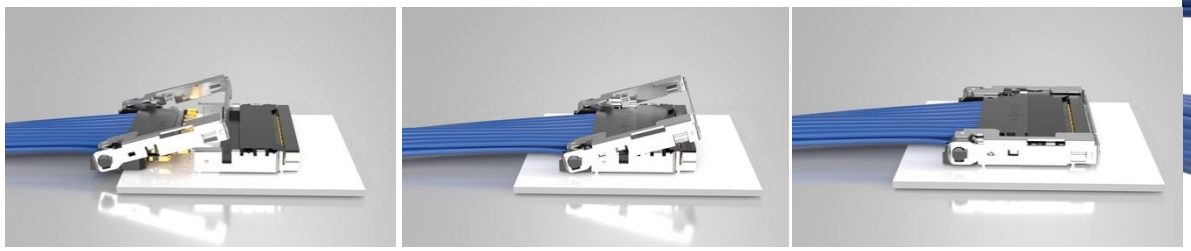
Ultra-High-Density Configuration Adjacent to the IC Package

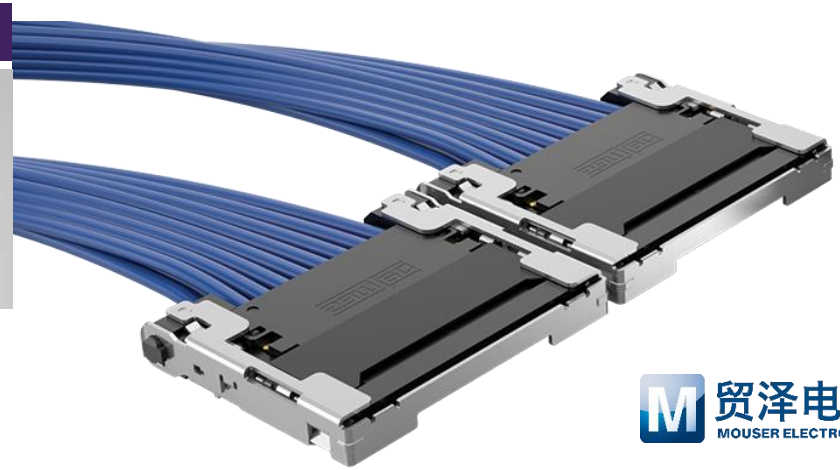
- Up to 16 pairs in an incredibly low 3.8 mm profile
- An extremely low profile allows Si-Fly™ connectors to reside under heat sinks or other cooling hardware
- Co-packaged interconnect option eludes the BGA and routes signals from the silicon package through a long-reach cable, supporting 5x the signal reach of traditional PCB solutions
- Extreme channel performance enabling 25.6 TB aggregate with a path to 51.2 TB
- 112 Gbps PAM4 per lane

SI-FLY™

PAM4 112 Gbps

SI-FLY™ Mating Step 1, 2, 3





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FLYOVER OPTIMAL END 2 "ADJACENT-TO-CHIP PACKAGE" OPTIONS

HIGHEST DENSITY

PAM4 56 Gbps → PAM4 112 Gbps

112G PAM4 Capable

ACCELERATE®

Right-Angle Plug

- 8 DP
- 16DP
- 24 DP

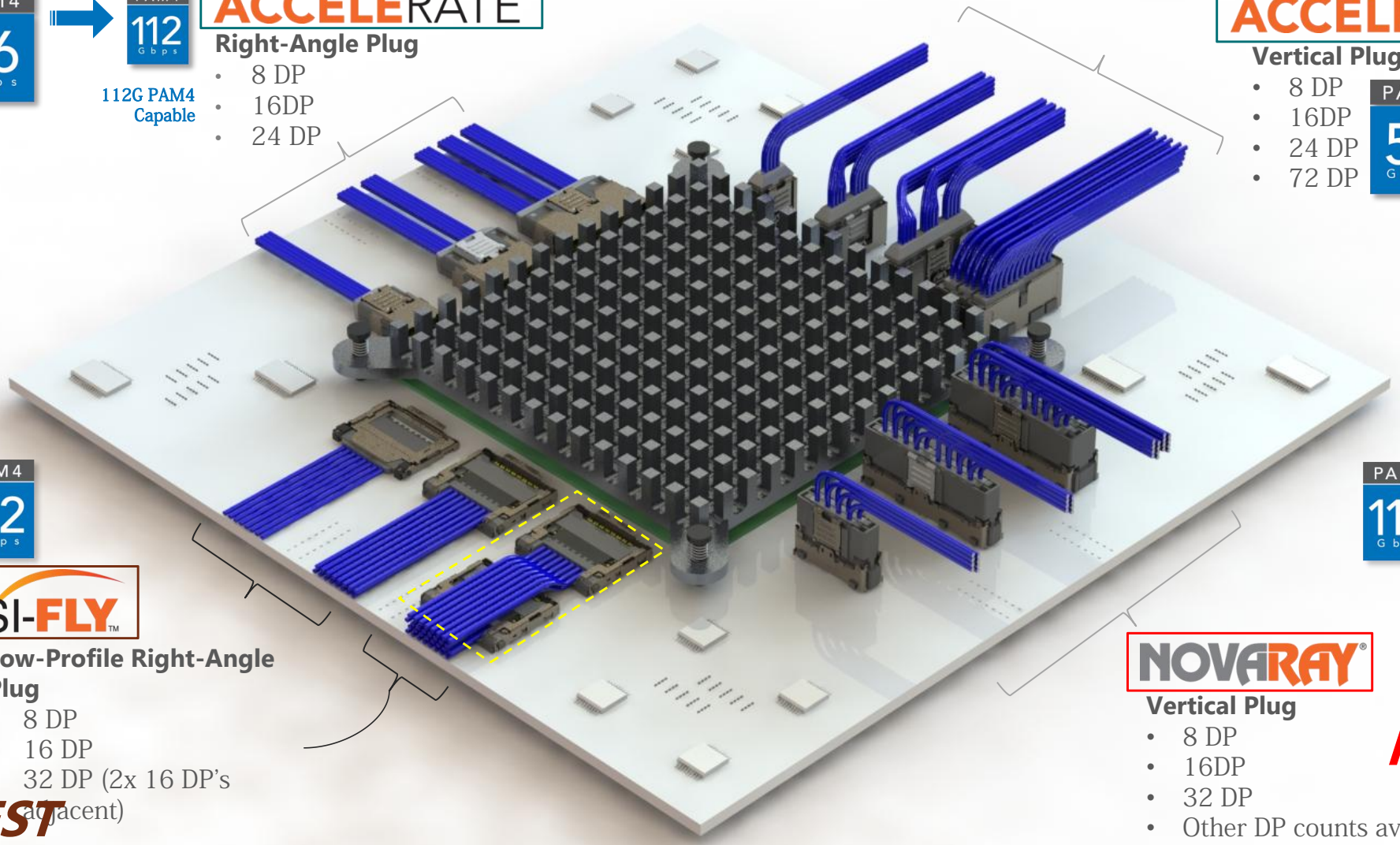
ACCELERATE®

Vertical Plug

- 8 DP
- 16DP
- 24 DP
- 72 DP

PAM4 56 Gbps → PAM4 112 Gbps

112G PAM4 Capable



PAM4 112 Gbps

SI-FLY™

Low-Profile Right-Angle Plug

- 8 DP
- 16 DP
- 32 DP (2x 16 DP's adjacent)

PAM4 112 Gbps → PAMX 224 Gbps

NOVARAY®

Vertical Plug

- 8 DP
- 16DP
- 32 DP
- Other DP counts available

LOWEST PROFILE

HIGHEST PERFORMANCE

samtec

FIREFLY™ MICRO FLYOVER SYSTEM™

FIREFLY™ COPPER SYSTEMS

High-performance, high-density copper Samtec Flyover® solution

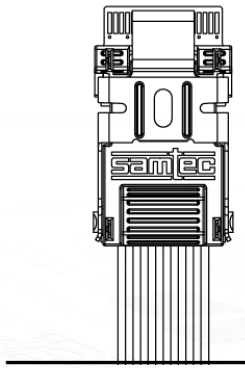
Pin compatible with FireFly® optical using the same connector system (ECUO)

x4, x8 and x12 configurations

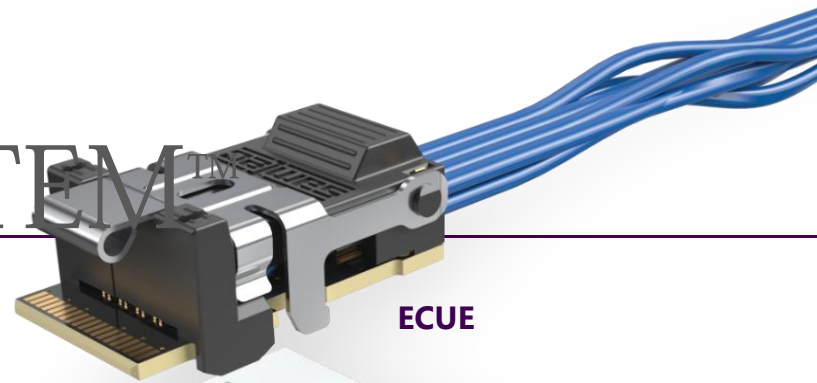
PCIe® 4.0 system (PCUE)

FIREFLY™

28 Gbps

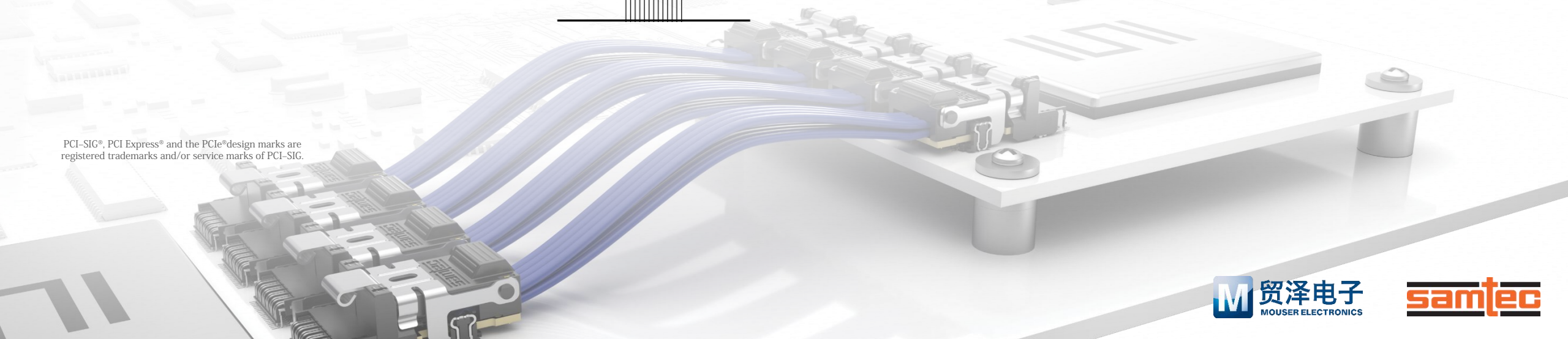


ECUE (x12)



ECUE

UEC5/UCC8



贸泽电子 MOUSER ELECTRONICS

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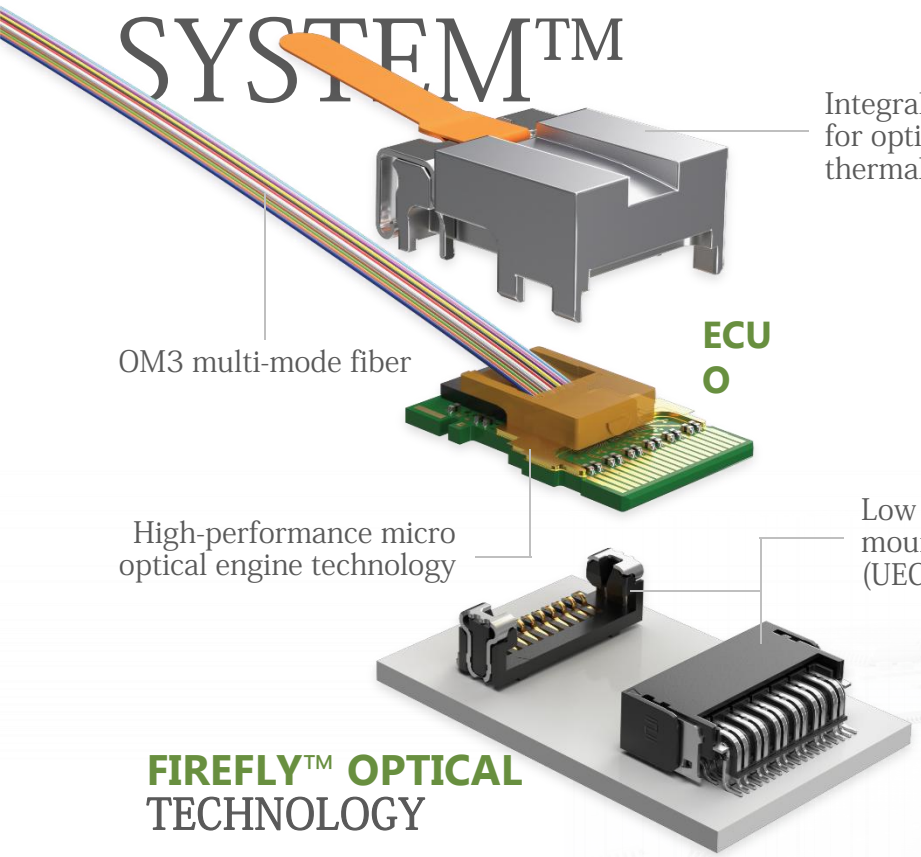
FIREFLY™ OPTICAL MICRO FLYOVER SYSTEM™



Data connection is taken “off board,” simplifying board layout and enhancing signal integrity from IC to faceplate

Industry leading miniature footprint allows for higher density close to the data source

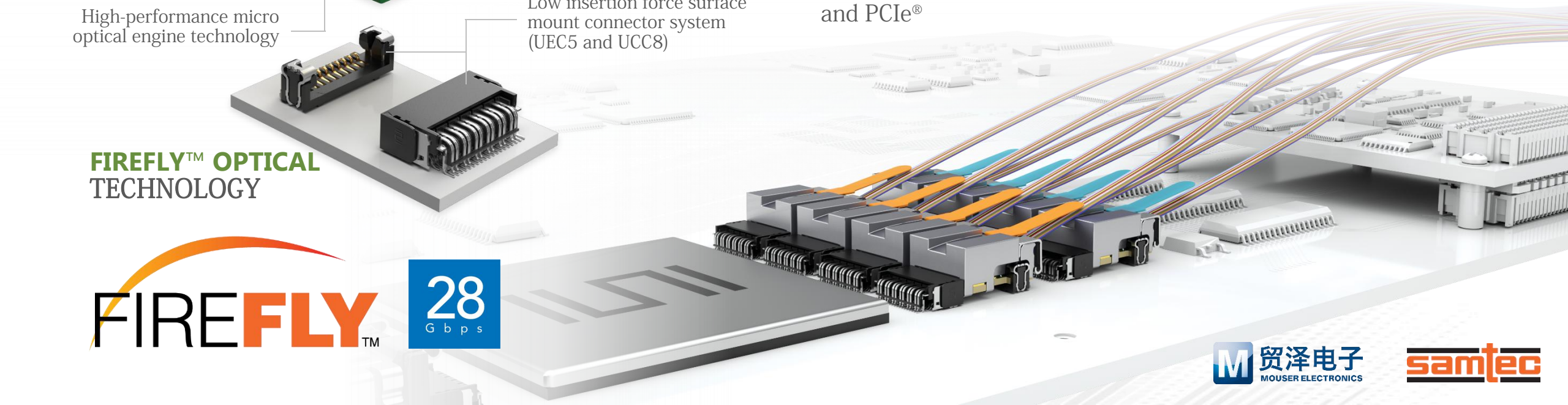
Rugged, simple to use system with easy insertion/removal and trace routing

Supports data center, HPC and FPGA protocols, including 10/40/100 GbE Ethernet, InfiniBand™, Fibre Channel, Aurora and PCIe®

FIREFLY™ OPTICAL TECHNOLOGY

FIREFLY™

28 Gbps



贸泽电子 MOUSER ELECTRONICS

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RF SOLUTIONS

High-Frequency, Precision RF (> 18 GHz) **& Low Frequency, Standard RF** (< 18 GHz)

CABLE ASSEMBLIES CABLE CONNECTORS BOARD CONNECTORS ORIGINAL

贸泽电子 MOUSER ELECTRONICS

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PRODUCT OVERVIEW

50 Ohm | 75 | 100

HIGH-FREQUENCY, PRECISION

2.40 mm, SMPM, 2.92 mm	**RF23C**
3.50 mm	**RF23S**
SMA, SMP	**RF25S**
2.40 mm, 2.92 mm	**RF120**
SMA, SMP	**RF405**
SMA	**RF402**
1.35 mm, 1.85 mm, 2.40 mm, SMPM, 2.92 mm	**RF047-A**
2.40 mm, 2.92 mm	**RF085**
1.85 mm, 2.40 mm, SMPM, 2.92 mm	**RF086**
SMA, TNCA, N Type	**RF180**
SMA, TNCA, N Type	**RF280**
GHz: 20, 40, 50, 70	**Bulls Eye®**

LOW-FREQUENCY, STANDARD RF

MHF (U.FL, W.FL), SMA	**MH081**
MHF (U.FL), SMA	**MH113**
HMHF1 (U.FL), SMA	**RF047**
MMCX, MCX, SMA, SMB, BNC, TNC, N Type	**RF178**
MMCX(V), MCX, SMA, SMB, BNC, TNC, N Type	**RF174** **RF316**
IsoRate®	**IJ5C**
MMCX, MCX, SMA, SMB	**IJ5H** (IsoRate® hybrid)
MMCX(V), MCX, SMA, SMB, BNC, TNC, N Type, Micro-Mini Ganged	**GRF1-C, GRF1H-C** (hybrid/ganged)
MMCX, MCX, SMA, BNC, TNC	**RS316**
SMA, TNC, N Type	**RF058**

MCX, MMCX, SMB, BNC, DIN 1.0/2.3	**RF179**
MCX, MMCX, SMB, BNC, DIN 1.0/2.3, Micro-Mini Ganged	**GRF7H-C** (hybrid ganged)
Micro-Mini Ganged	**GRF7-C**
HD-BNC™, DIN 1.0/2.3	**RFB8T, RFC8T**
BNC, HD-BNC™, DIN 1.0/2.3	**RFA6T, RFC6T**
BNC, HD-BNC™, DIN 1.0/2.3	**RFB6T**

CJT (original)	**C28S**

CABLE ASSEMBLIES
+
BOARD CONNECTORS
+
CABLE CONNECTORS

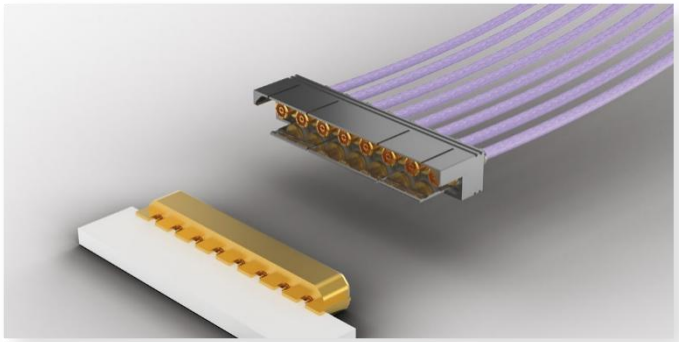
RF COUPLING TYPES

PUSH-ON

- Quick attach
- High volume / high cycle & blind-mate applications
- Compensates for axial & radial misalignment (SMPM, SMP)

THREADED

- Larger, more robust
- Interoperability between (some) interface standards
- Superior repeatability, high mechanical stability



GANGED SOLUTIONS

- Push-on connectors / quick attach
- More channels
- High density applications

TEST & MEASUREMENT

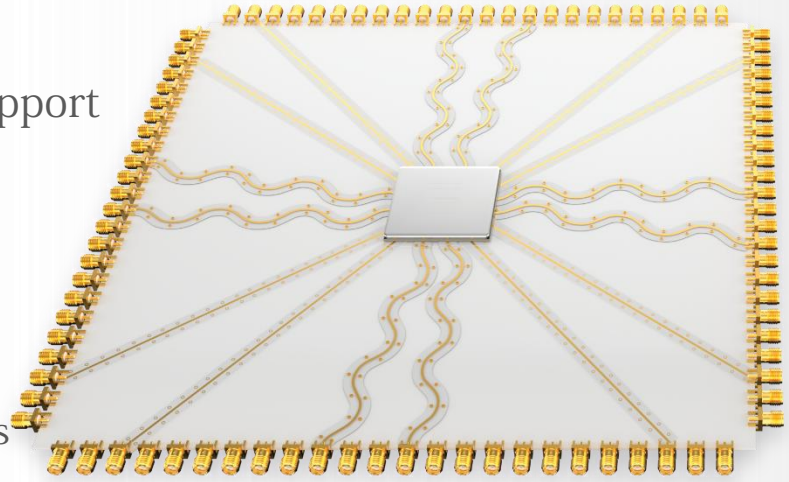
OPTIMIZED PERFORMANCE TO 70 GHz

Bulls Eye® High-Performance Test

The high-density array designs and advanced cabling solutions within Samtec's Bulls Eye® product family support test and measurement applications to 70 GHz.

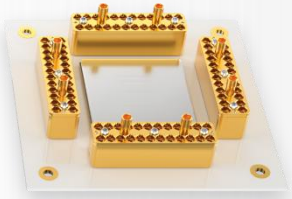
- Compression interface to the board provides easy on/off and eliminates soldering costs
- High-density, space-saving design
- Enables smaller evaluation boards and shorter trace lengths
- Installation: while the attach process for each series is similar, each have unique specifications that need to be observed
- Ideal for testing the latest silicon chips capable of 112 Gbps PAM4

Traditional with SMAs



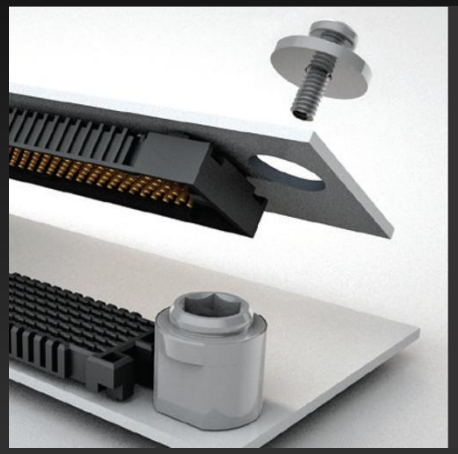
Enables smaller evaluation boards & shorter trace lengths

Bulls Eye®

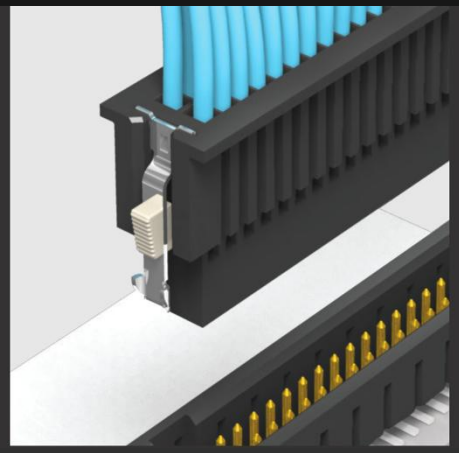


BULLSEYE®
TEST POINT SYSTEM

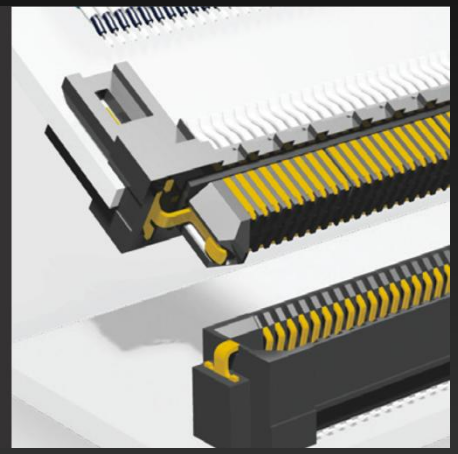
ROGGED FEATURES RUGGEDIZING OPTIONS



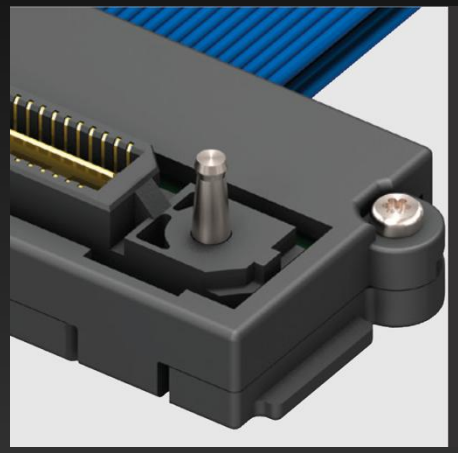
JACK SCREWS
Ideal for high normal force, zippering and other rugged applications



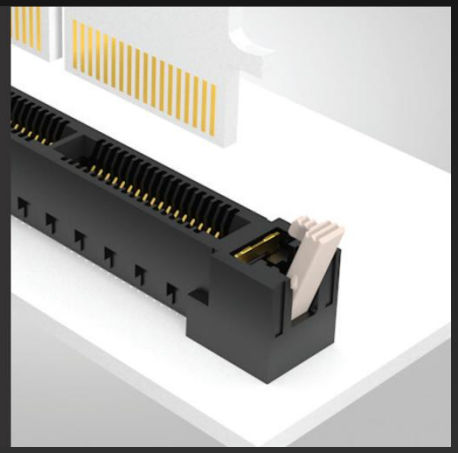
POSITIVE LATCHING
Manually activated latches increase unmating force by up to 200%



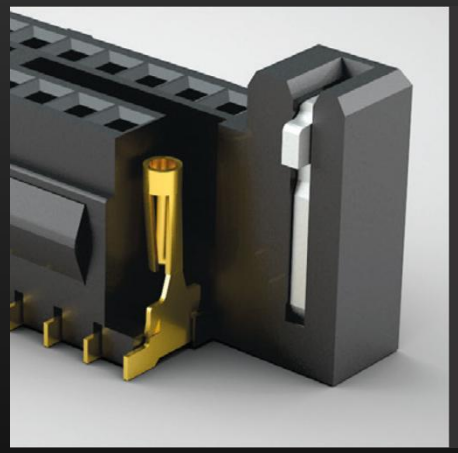
FRICTION LOCKS
Metal or plastic friction locks increase retention/withdrawal force



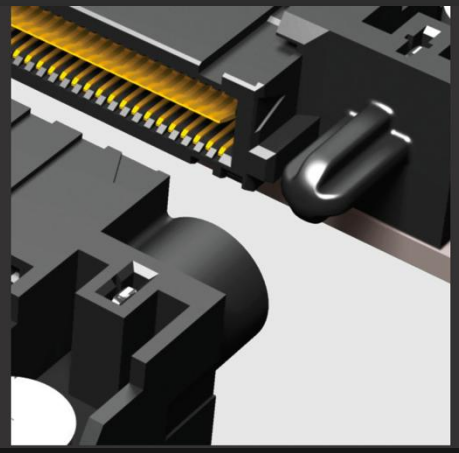
RETENTION PINS
Increase unmating force by up to 50%



BOARD LOCKS
Boards are mechanically locked together

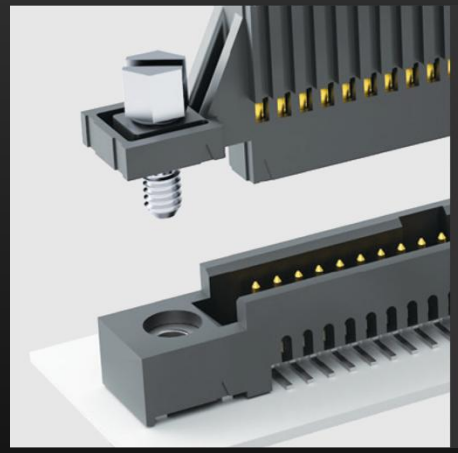


WELD TABS
Significantly increase sheer resistance of connector to PCB

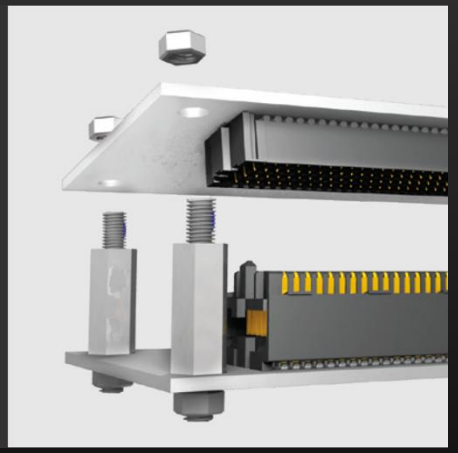


GUIDE POSTS
Easy and secure mating

SHIELDING
360° shielding reduces EMI



SCREW DOWNS
Secure mechanical attachment to the board



BOARD STANDOFFS
Precision machined standoffs for
5 mm to 25 mm board

ULTRA RUGGED TESTING

EXTENDED LIFE PRODUCT™ TESTING & SEVERE ENVIRONMENT TESTING

E.L.P.™ products are tested to rigorous standards, which evaluate contact resistance in simulated storage and field conditions.

- 10 years Mixed Flowing Gas (MFG)
- High Mating Cycles (250 to 2,500)
- Certain plating and/or contact options will apply

SET TESTING INCLUDES

- Mating/Unmating/Durability
- Mechanical Shock/Random Vibration/LLCR & Nanosecond Event Detection
- Temperature Cycling
- Non-Operating Class Temperature
- DWV at Altitude
- Electrostatic Discharge (ESD)
- Outgassing

NASA

Samtec's SET products are approved for NASA Class D missions that require high-reliability, quick-turn and cost-effective solutions for LEO and GEO satellites, SmallSats, CubeSats and other space exploration applications.

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ULTRA MICRO POWER

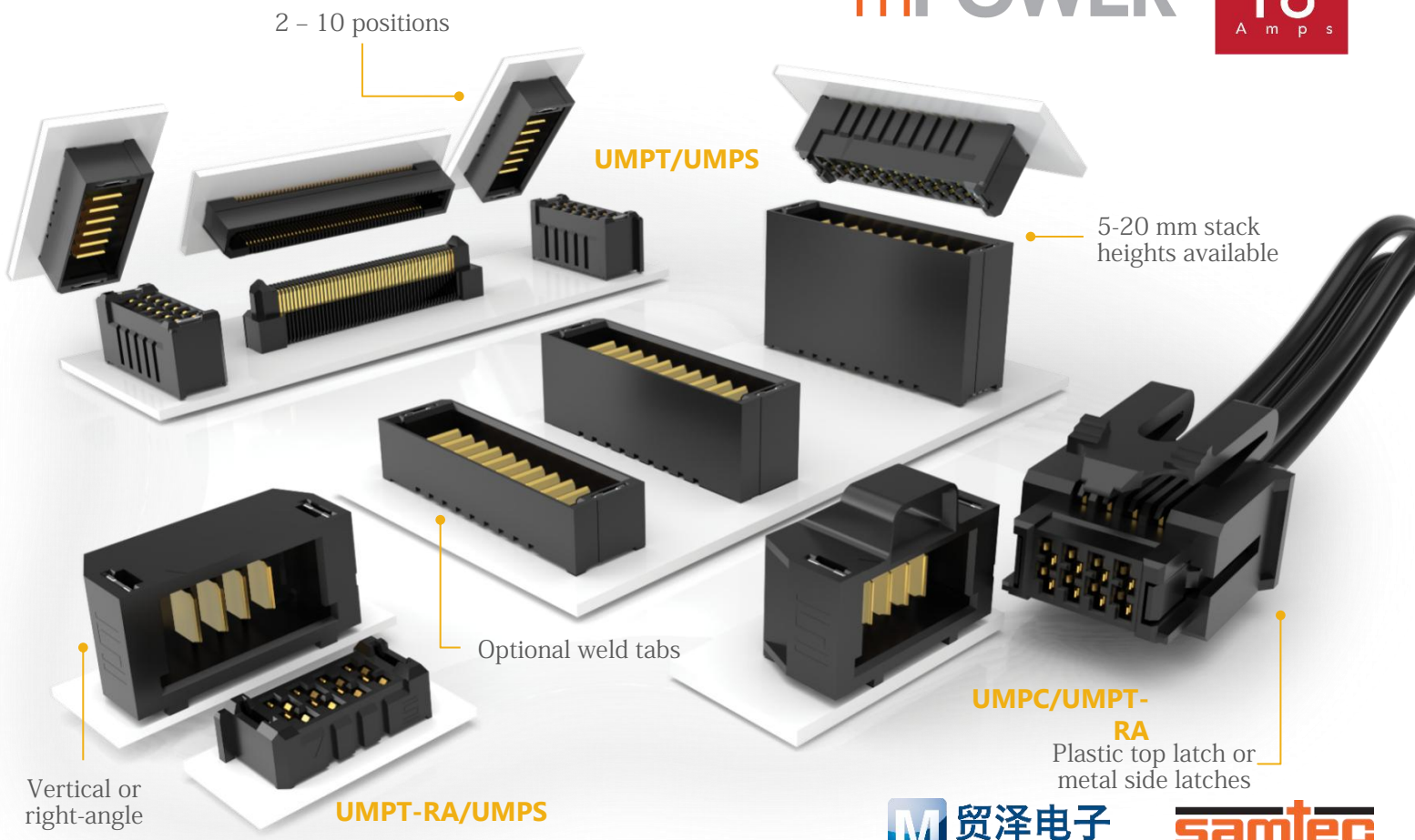
18 A PER BLADE • MICRO 2.00 mm PITCH • DESIGN FLEXIBILITY

2.00 mm PITCH mPOWER®

- Use with Samtec's high-speed connector systems for a unique power/signal system.
- Tin or 10 µ" Gold plated power blades; 30 µ" Gold plating available to meet specific regulations.
- Latch option for mating with cable assembly.
- Standard creepage (2.20 mm) and clearance (1.65 mm).

UMPT shown at 4 total positions

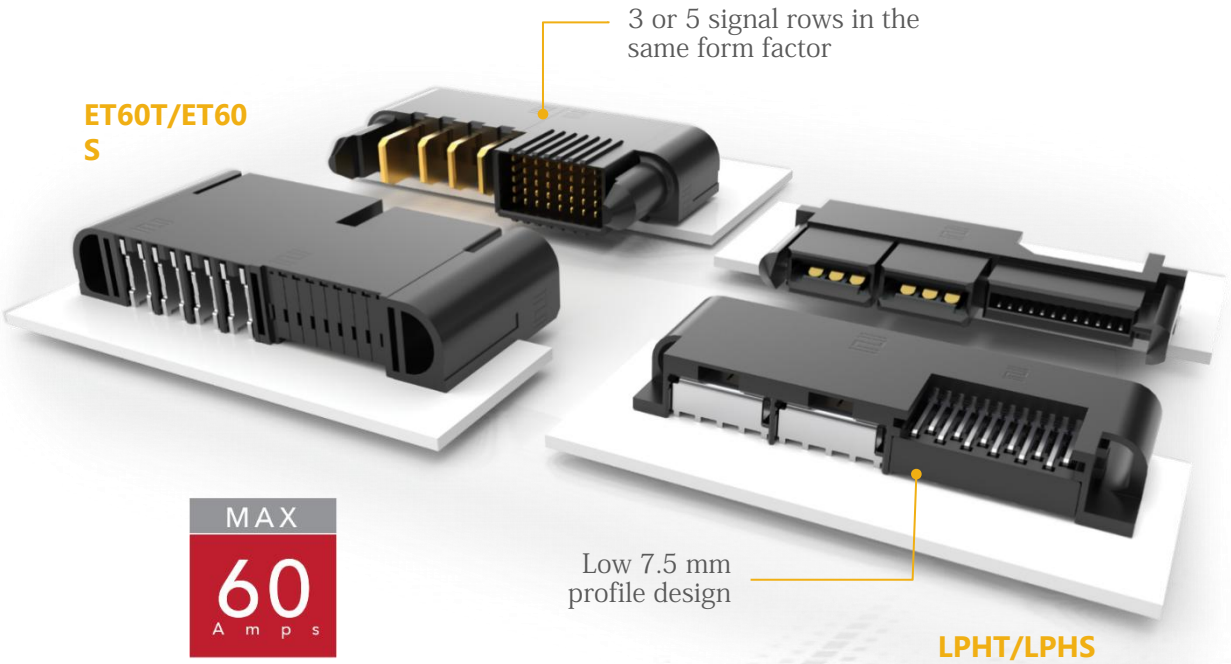
mPOWER® MAX 18 Amps



HIGH-POWER

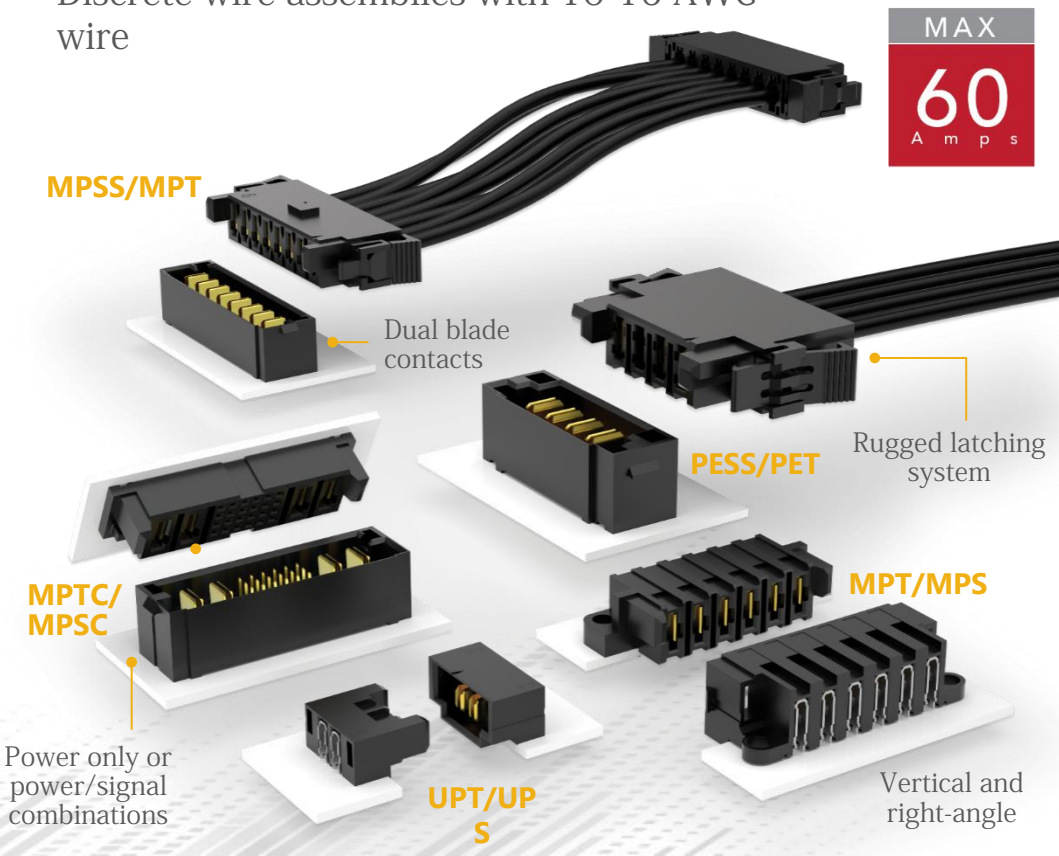
EXTREME POWER

- AC or DC power, AC-DC combos and split power options (ET60T/ET60S)
- High-density, double stacked power blades (LPHT/LPHS)



POWERSTRIP™ SYSTEMS

- 23.5 A/blade to 58.7 A/blade (1 blade powered)
- 3.81 mm, 5.00 mm and 6.35 mm pitch
- Discrete wire assemblies with 10-16 AWG wire



FLEXIBLE **STACKING**

INCREDIBLE FLEXIBILITY

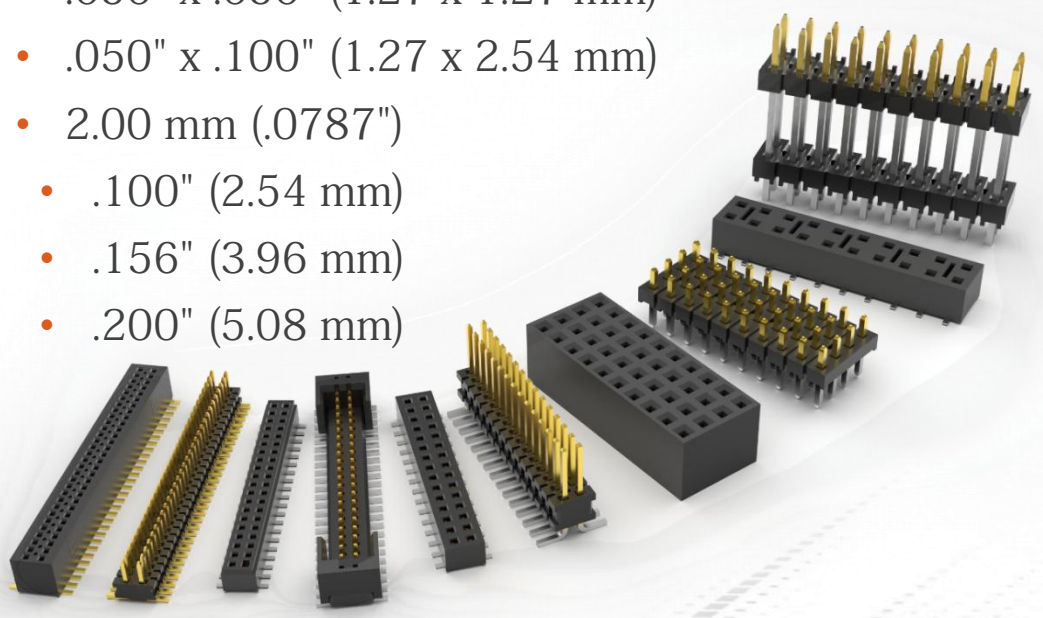
- Post height: Adjustable in .005" (0.13 mm) increments
- Body positions: Adjustable in .005" (0.13 mm) increments
- Board stacking distance: 1.65 mm (.065") - 48.51 mm (1.910")
- Number of pins: 2-300
- Number of rows: 1-6

CUSTOMIZABLE

- Mix-and-match headers and sockets to find the right solution
- Quick and easy custom parts are available

VARIETY OF PITCHES

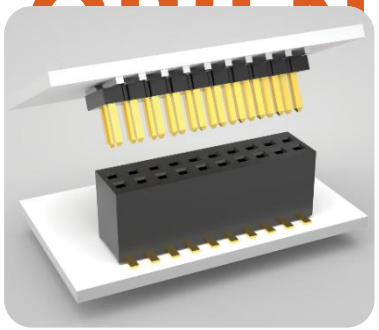
- 0.80 mm (.0315")
- 1.00 mm (.0394")
- .050" (1.27 mm)
- .050" x .050" (1.27 x 1.27 mm)
- .050" x .100" (1.27 x 2.54 mm)
- 2.00 mm (.0787")
- .100" (2.54 mm)
- .156" (3.96 mm)
- .200" (5.08 mm)



BUILD IT YOURSELF

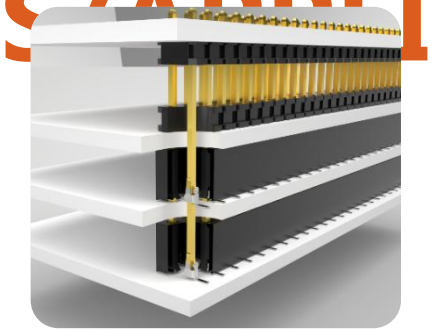
Check out **Solutionator**® to quickly build a mated set for your specific application.

VARIETY OF ORIENTATIONS/APPLICATIONS



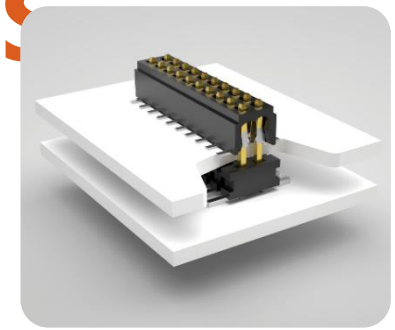
Standard

- Choice of contact system
- Single, double and triple row designs
- Largest variety



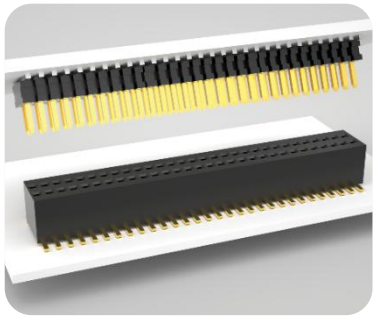
Pass-Through

- Connect three or more boards
- Tiger Claw™ & Tiger Beam™ contact systems
- Surface mount or offset through-hole



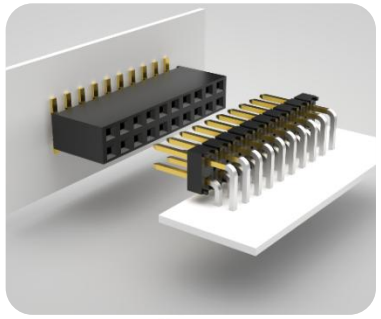
Bottom Entry

- Tiger Claw™ contacts
- Access to components when mated
- Space savings



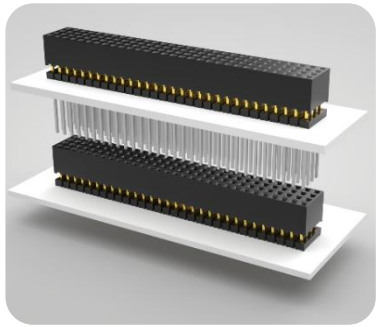
Low Profile

- Down to 1.65 mm (.065") stack height
- Tiger Claw™ contacts
- Space saving



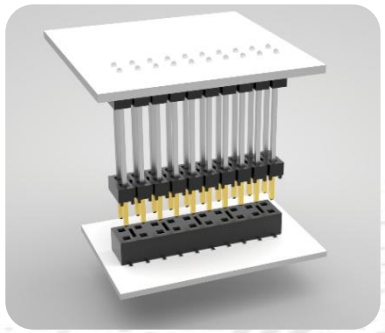
Right-Angle

- Design flexibility
- Tiger Claw™ & Tiger Buy™ contacts
- Through-hole, surface mount



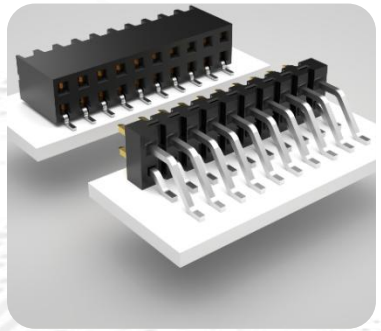
Self-Nesting

- Tiger Buy™ contacts
- Press-fit or through-hole tails
- PC/104-Plus™ embedded applications



Elevated

- Up to 48.51 mm (1.910") stack height
- Design flexibility
- Clearance, air flow



Coplanar

- 1-4 row designs
- Surface mount, through-hole or mixed technology
- Tiger Claw™ & Tiger Beam™ contacts

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SUDDEN SERVICE®

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Seven Qi (seven.qi@samtec.com), FAE, Base in Shenzhen

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